

Project: IEEE P802.15 Working Group for Wireless Personal Area Networks (WPANs)

Submission Title: Circuits and Systems for Mobile Terahertz Imaging and Sensing Applications

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Re: n/a

Abstract: [The talk will address the vision for future mobile THz imaging and sensing applications as part of the MARIE Transregio (TRR) 196, a Collaborative Research Center (CRC) funded by the German Research Foundation (DFG). The talk summarizes the MARIE challenges, research questions and outlook for 2024. It includes examples for compact systems on a chip for future mobile applications, such as a wideband THz spectroscopy system a chip, compact THz cameras and sources in silicon technologies, and mobile bio-medical applications.]

Purpose: Information of IEEE 802.15 SC THz

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Circuits and Systems for Mobile Terahertz Imaging and Sensing Applications

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(IHCT)**

University of Wuppertal



UNIVERSITÄT
DUISBURG
ESSEN

Open-Minded

RUHR
UNIVERSITÄT
BOCHUM **RUB**



Collaborative Research Center (CRC) / Transregio (TRR) 196

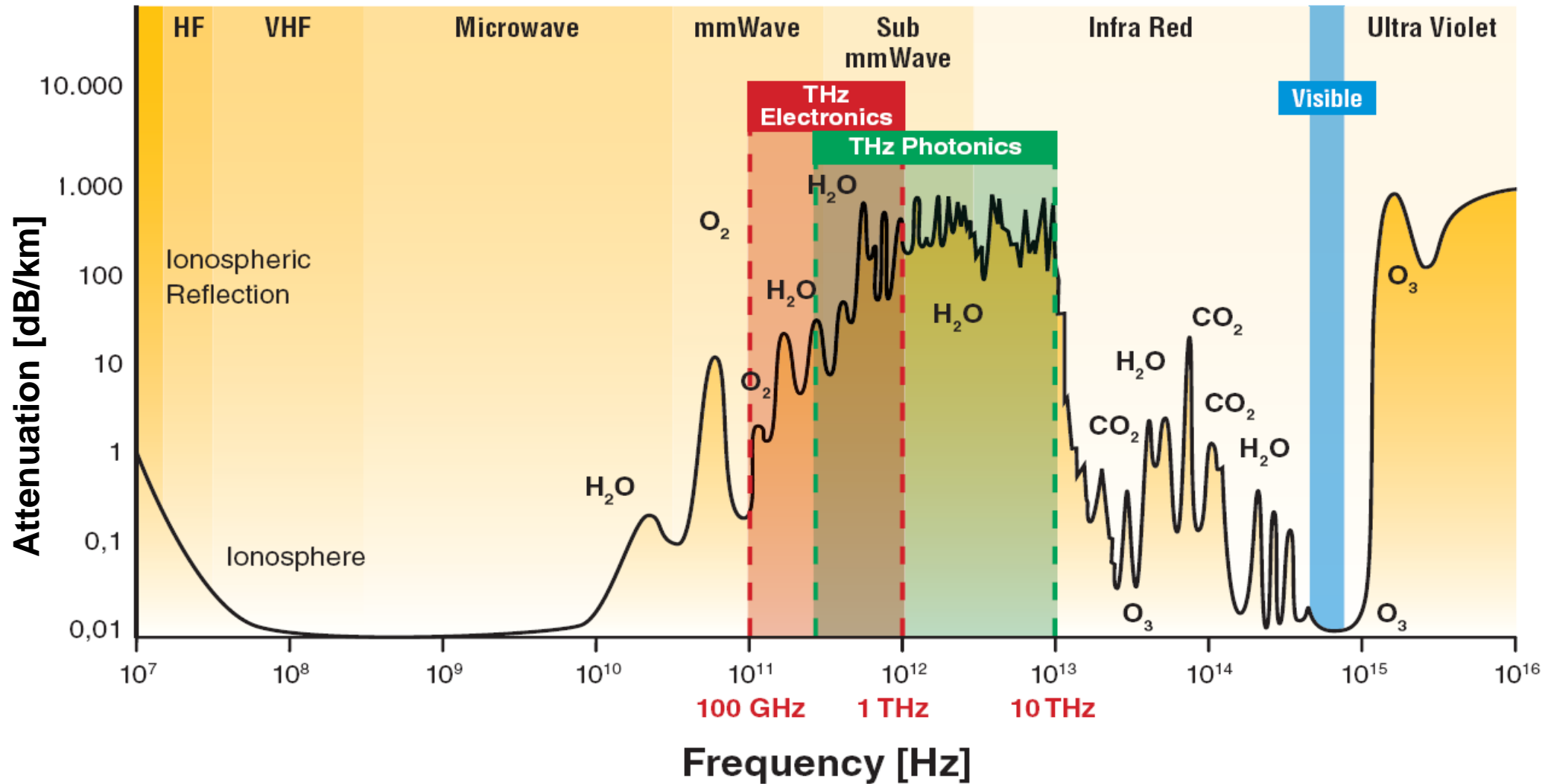


Mobile Material Characterization and Localization by
Electromagnetic Sensing

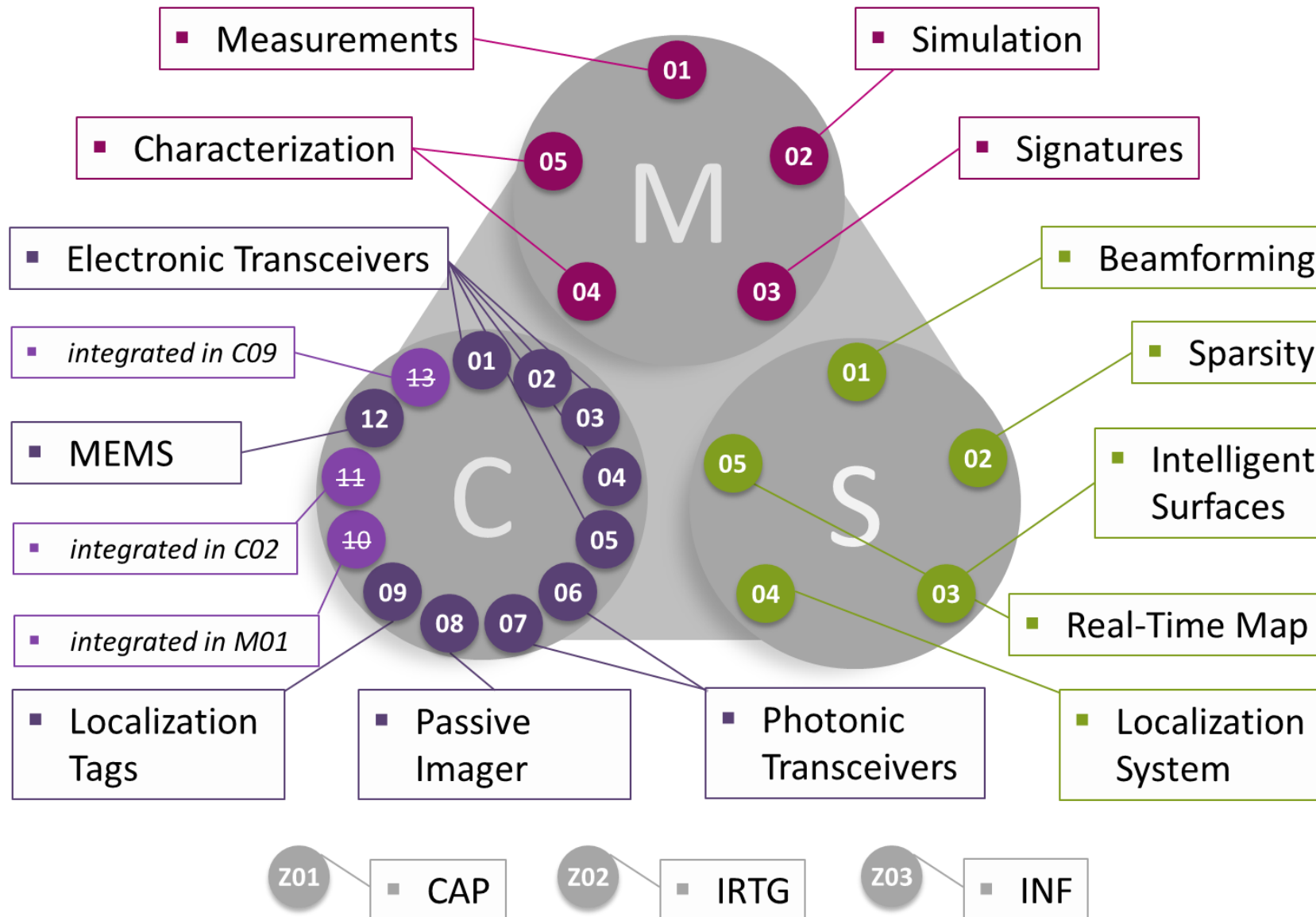
Outline

- MARIE: Collaborative Research Center (CRC) / Transregio (TRR) 196
 - Vision for future mobile THz imaging and sensing applications
 - Marie challenges
 - Research questions
 - Outlook for 2024
- Mobile Circuits and Systems Examples
 1. Wideband THz spectroscopy system a chip
 2. Compact THz cameras and sources in silicon technologies
 3. Mobile bio-medical applications
- Summary

MARIE Project Overview

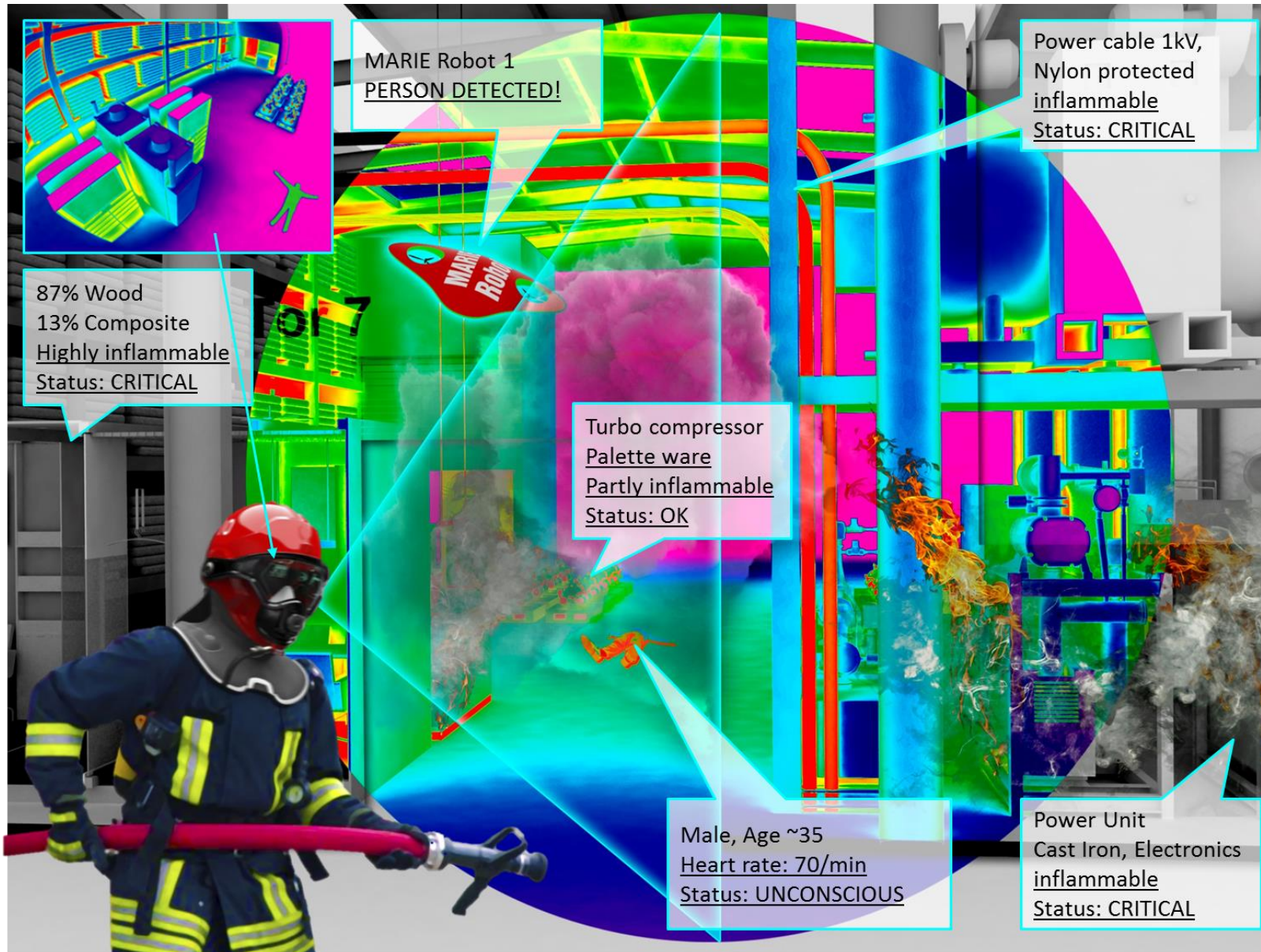


MARIE Project Overview



- Facts Sheet:**
- 2017 – 2024 (2028)
 - 20 Projects, 26 PIs
 - 83 Journal Papers
 - 226 Conference Papers
 - 1st Period: 12.8 M€
 - 2nd Period: 13.7 M€
 - Funded by the German Research Foundation (DFG)

MARIE Vision



What comes next for “Mobile Sensors” ?



1) Get Mobile!

Challenge 2 ... **Mobile Transceivers**

- microsystems (light-weight)
- fully-integrated (all the system needs)
- efficient (battery-operated)

2) In-room challenges



Challenge 3 ... **Mobile Material Characterization**

- sensitivity
- operation frequency
- bandwidth

Challenge 4 ... **Sub-mm Accurate Localization**

- Precision
- Scanning
- use natural environment, sensor fusion

“Static Labs: Chips from Technologies”

Initial Questions

01

Can we **synthesize**, clean, stable, and highly tunable (linear) **reference signals** for THz?

02

Can we **generate** THz on chip and lock it to a reference signal?

05

Can we **efficiently radiate** THz signals?

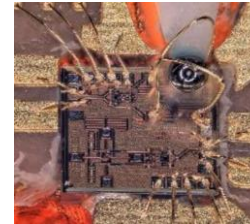
09

Can we realize **advanced THz passives** for localization?

03

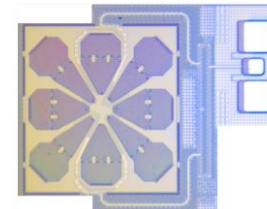
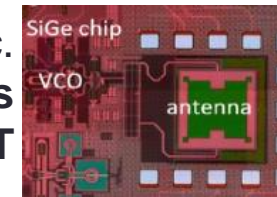
Can we **localize objects** in 3-D with a compact fully integrated MIMO radar?

Static Lab Highlights



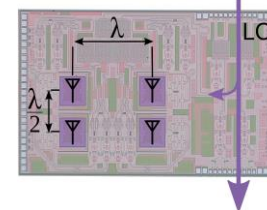
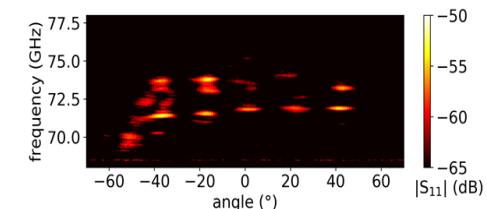
YIG-on-chip 20-48 GHz
-70dBc/Hz@1kHz

Injection locked osc.
InP **0.56THz RTDs**
InP **0.49THz HBT**



Design **recipes** & physical **insights**.

Photonic crystal
Luneburg lens



240GHz **MIMO radar**

“Static Labs: Chips from Technologies”

Initial Questions

07

Can we realize **photonic integrated circuits** for **1-D imaging**?

06

Can we invent novel **photonic THz spectroscopy systems** without mechanical delay lines?

04

Can narrow-band electronics measure broad band **spectral fingerprints** of materials?

12

Can we **steer a THz beam** passively?

08

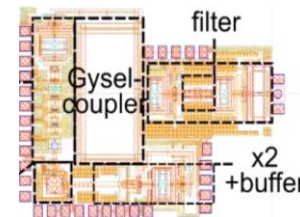
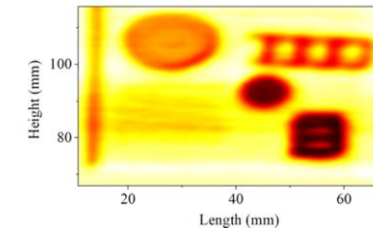
Is there a chance to **see the natural THz radiation** with a silicon THz camera and read a spectral fingerprint?

Static Lab Highlights



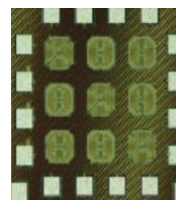
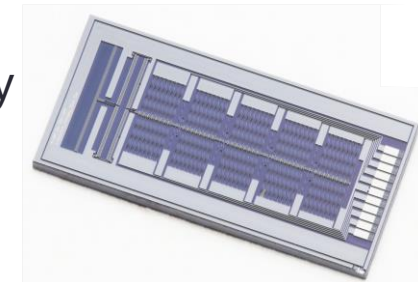
Heterointegrated antenna arrays for beam steering

Frequency-Domain THz system



Gapless spectral coverage over a **decade up to 1.5THz**

Digital 5-bit reflectarray reflector



NEP:
 $1.9\text{pW}/\sqrt{\text{Hz}}$

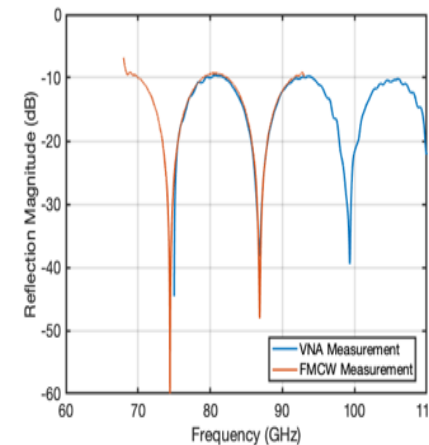
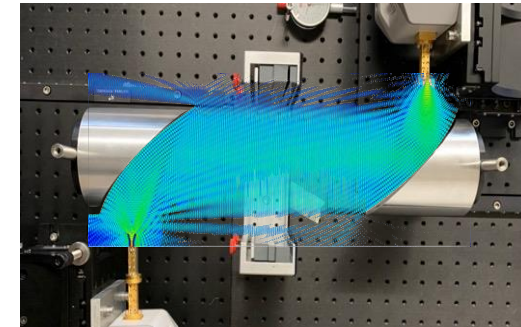
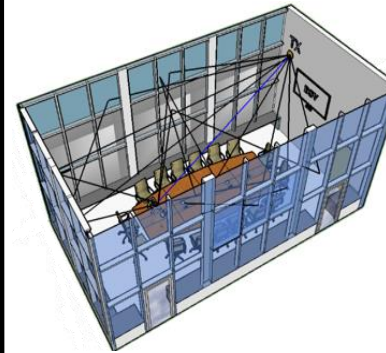
Static Lab “Models from Measurement”

Initial Questions

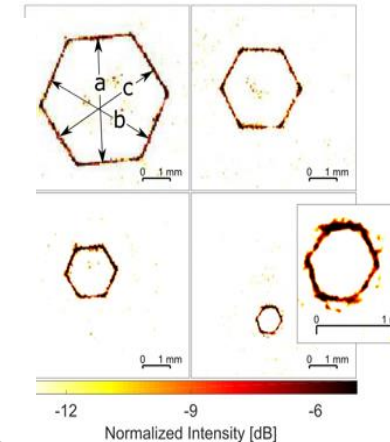
- 01 How to exploit the **THz range** by **propagation measurements** and **modeling**?
- 02 How to cover the **different scales** in **simulating** THz propagation?
- 03 How to set up an efficient multiscale EM model for **complex surface systems**?
- 04 How obtain spatial information on the EM **material properties** by **MIMO radar**?
- 05 How to use **ellipsometry** in **super-resolution** THz imaging to **characterize** materials?

Static Lab Highlights

Novel GO & PO sim. engines



FMCW calibration techn.



Lensless THz imaging

Static Lab “Systems from Concepts”

Initial Questions

01

How to extend **Beamforming Concepts** to THz Frequencies ?

02

How to model and compensate **MIMO THz System Imperfections** ?

03

How to design **Space Time Signaling** for MIMO THz Radar ?

04

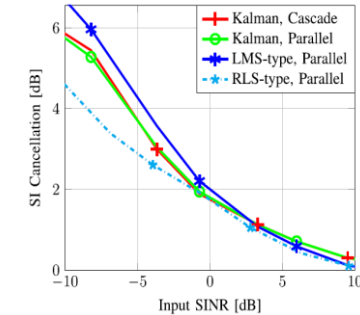
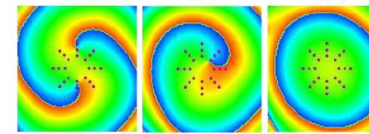
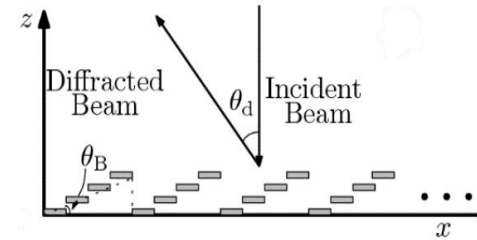
How to design a **Sub-mm Accurate Localization System** ?

05

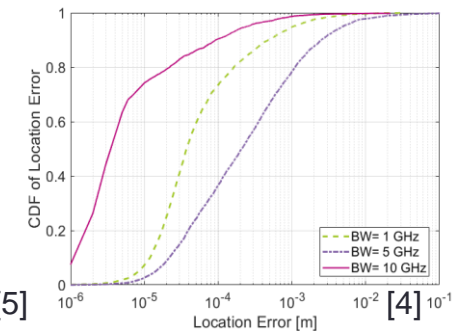
How to realize a **Real-Time Computing Platform** for THz Algorithms?

Static Lab Highlights

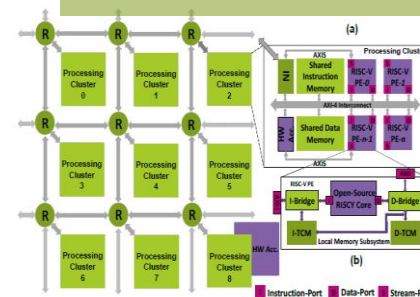
MEMS based Beam Steering



Self Interference Cancellation



MARIE Computing Architecture



What comes next for “Mobile Sensors” ?

Challenge 1 ... **Mobile Beamforming up to 5 THz Bandwidth**

Challenge 2 ... **MIMO THz Imperfections up to 5 THz**



Challenge 3 ... **Concept: First Real-Time Map**



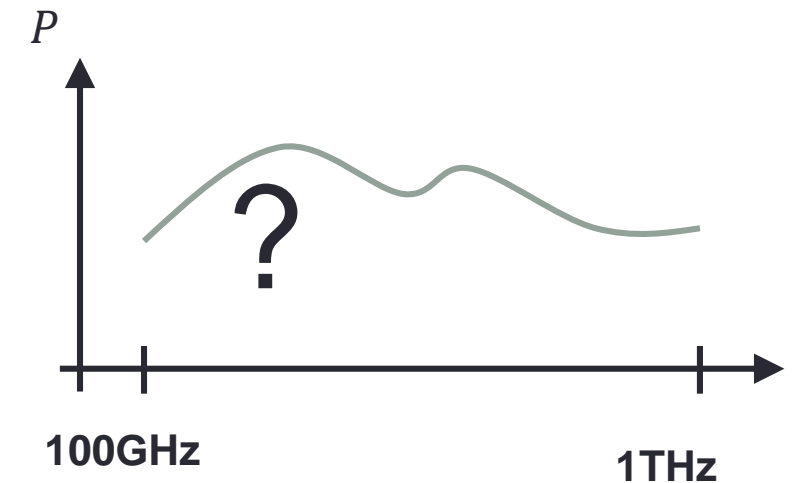
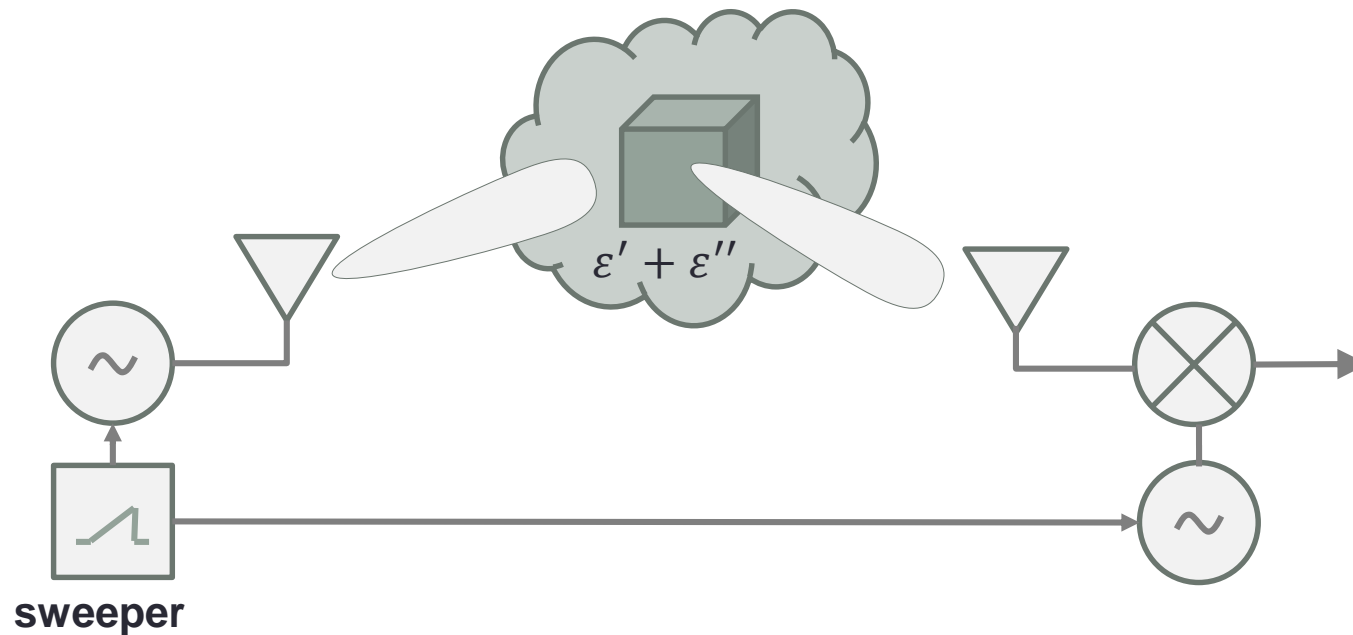
Challenge 4 ... **Proof: Sub-mm Accurate Localization**

Example 1: THz Spectroscopy

How about hyper spectral imaging and sensing?

Wanted:

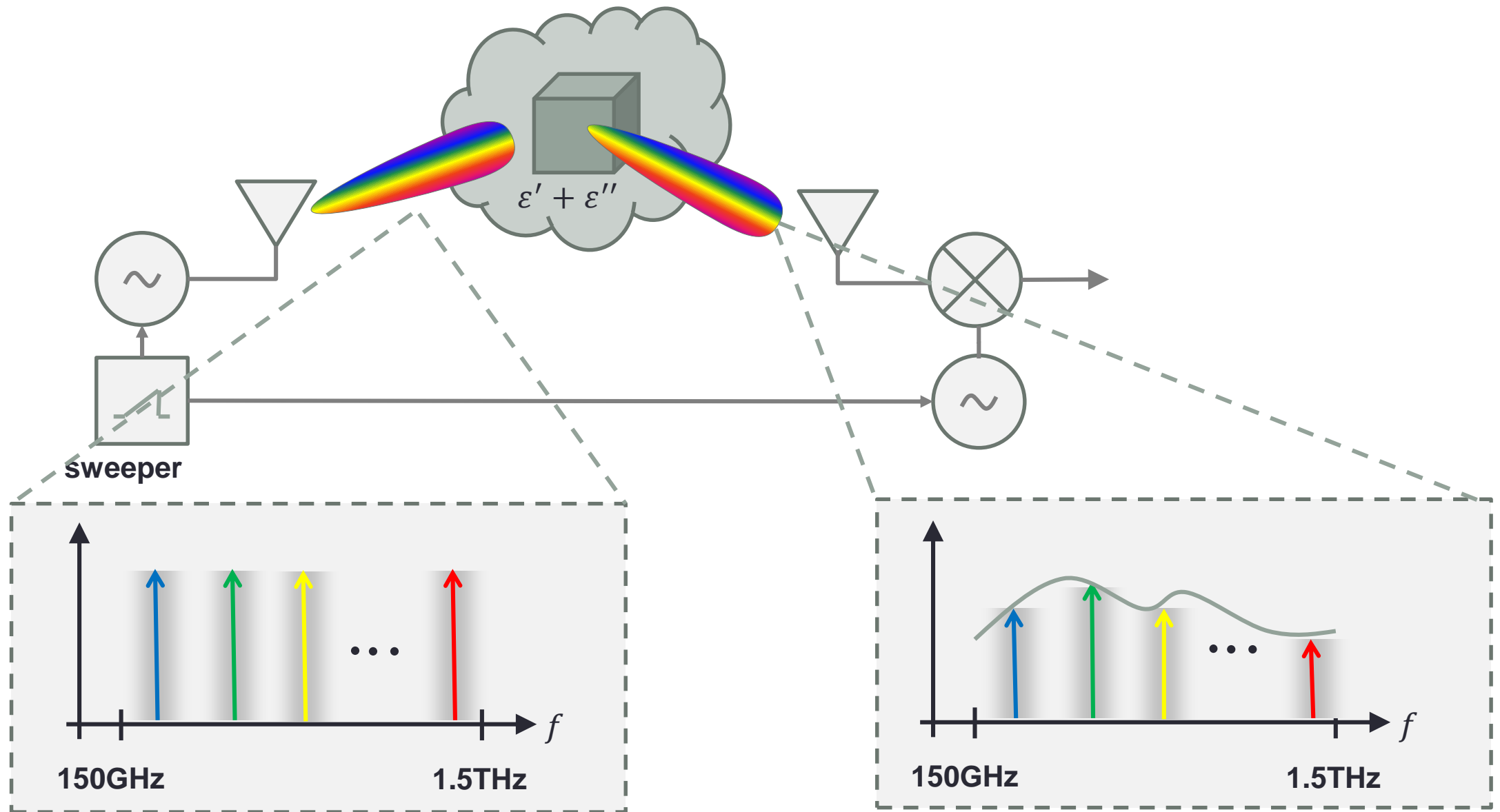
Materials spectral fingerprint
+
Polarization-diversity for ellipsometry



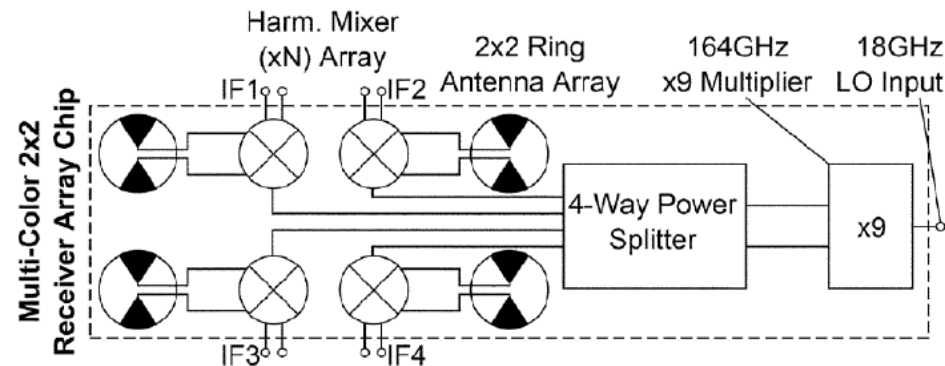
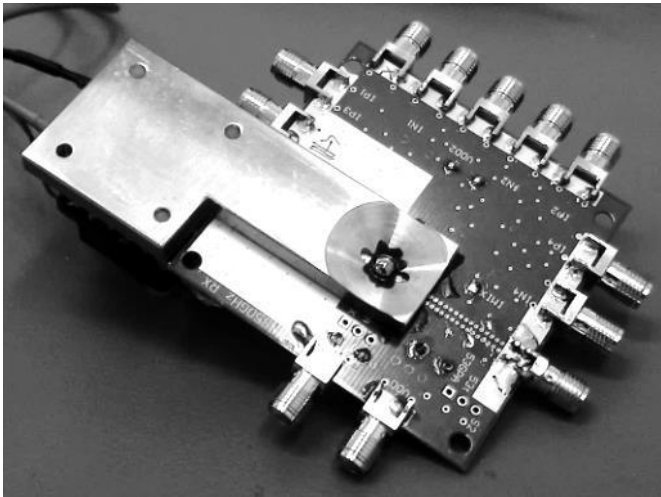
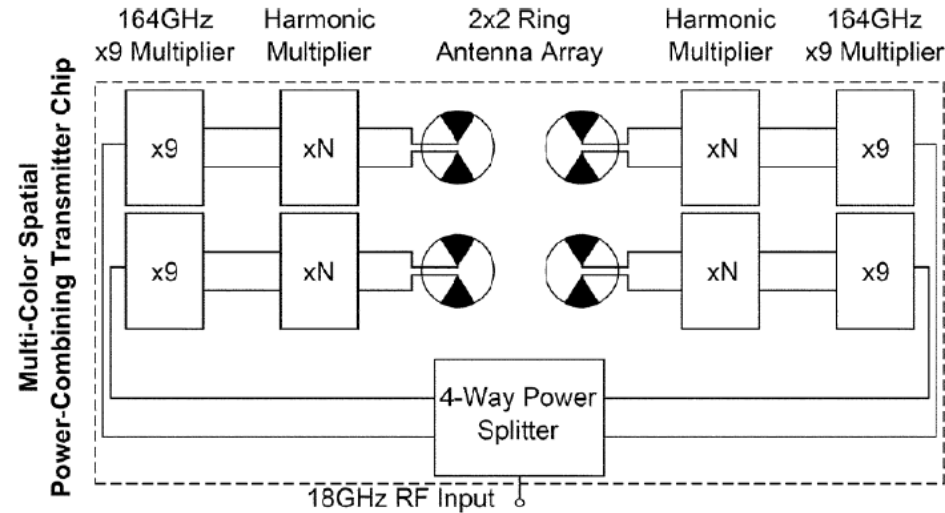
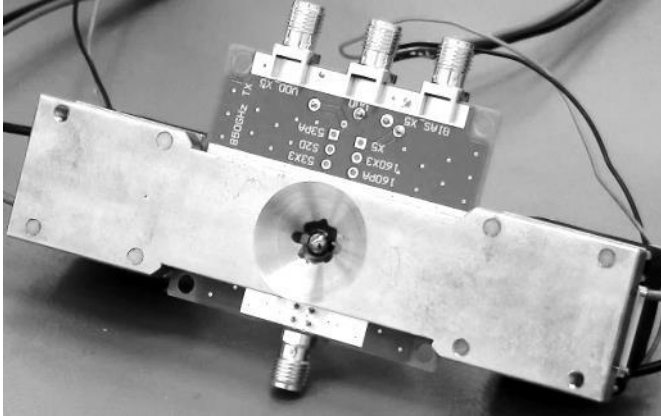
at least a decade of bandwidth!

Can we do this in a compact silicon-based coherent imager?

Hyper Spectral Imaging

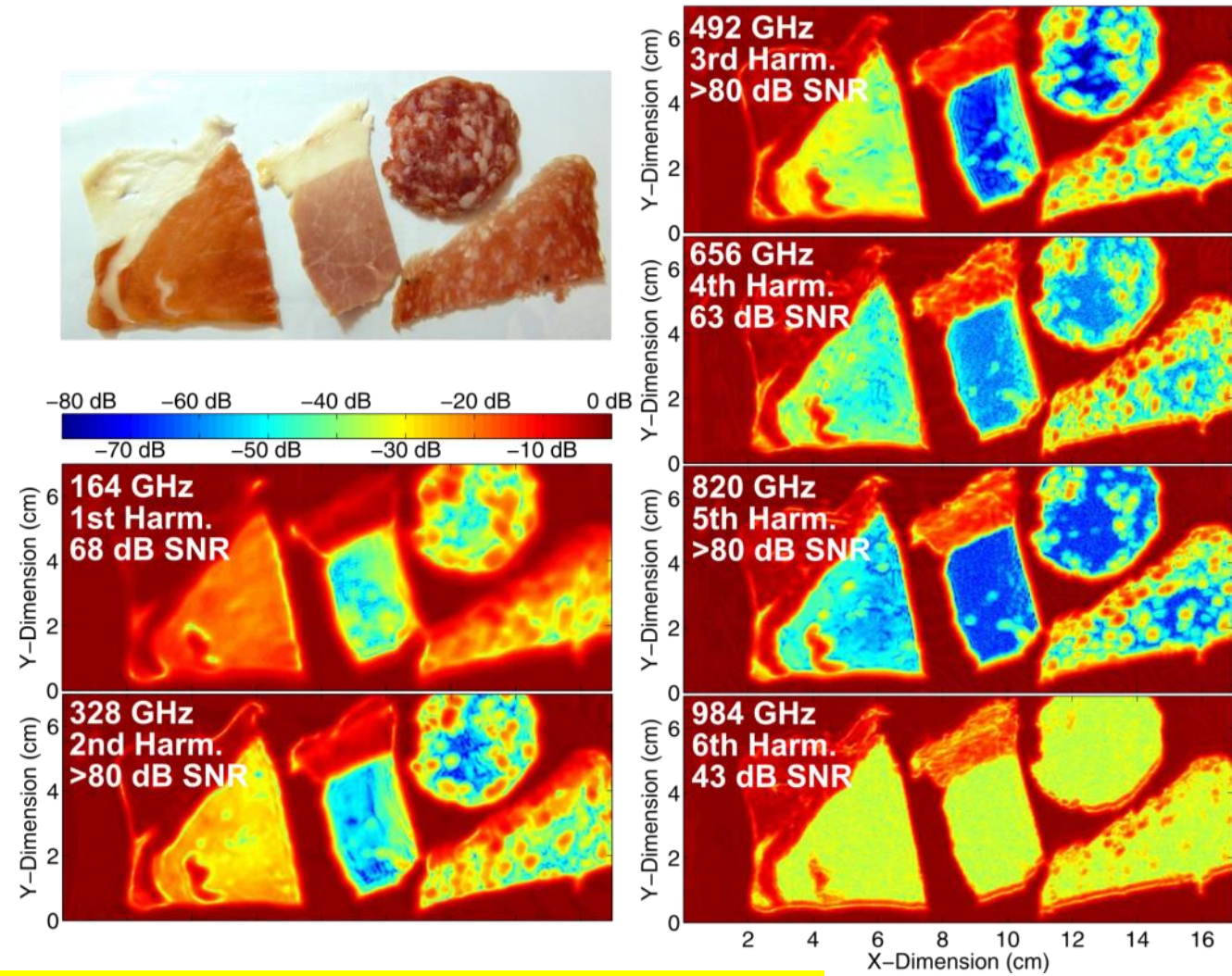
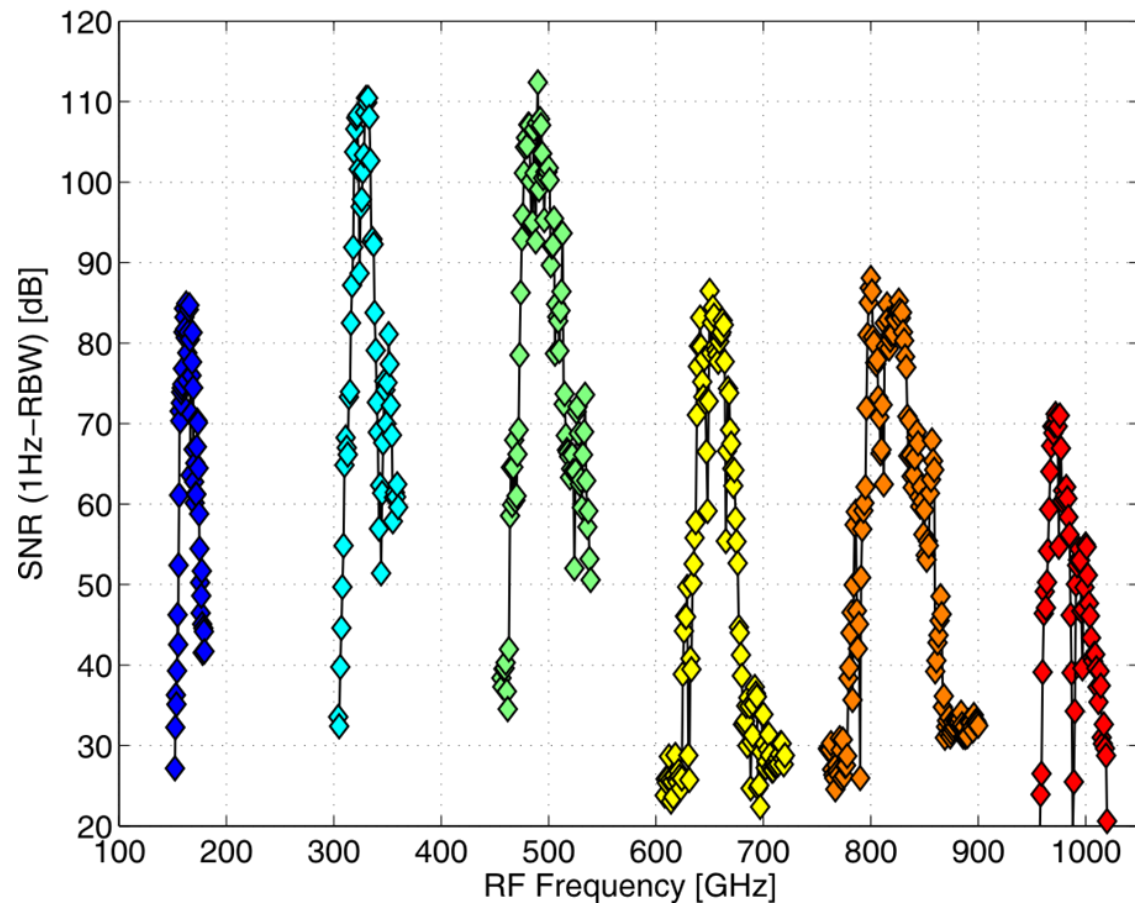


160-GHz to 1-THz Multi-Color SiGe Chip-Set



- Differential 825-GHz RF mixes with the 5th harmonic of a 162GHz LO
- CG= -15dB
- 4 freq. mult. Stages
- 4 ring antennas for spatial power combining
- 4.0 x 0.8 mm²

Imaging Results



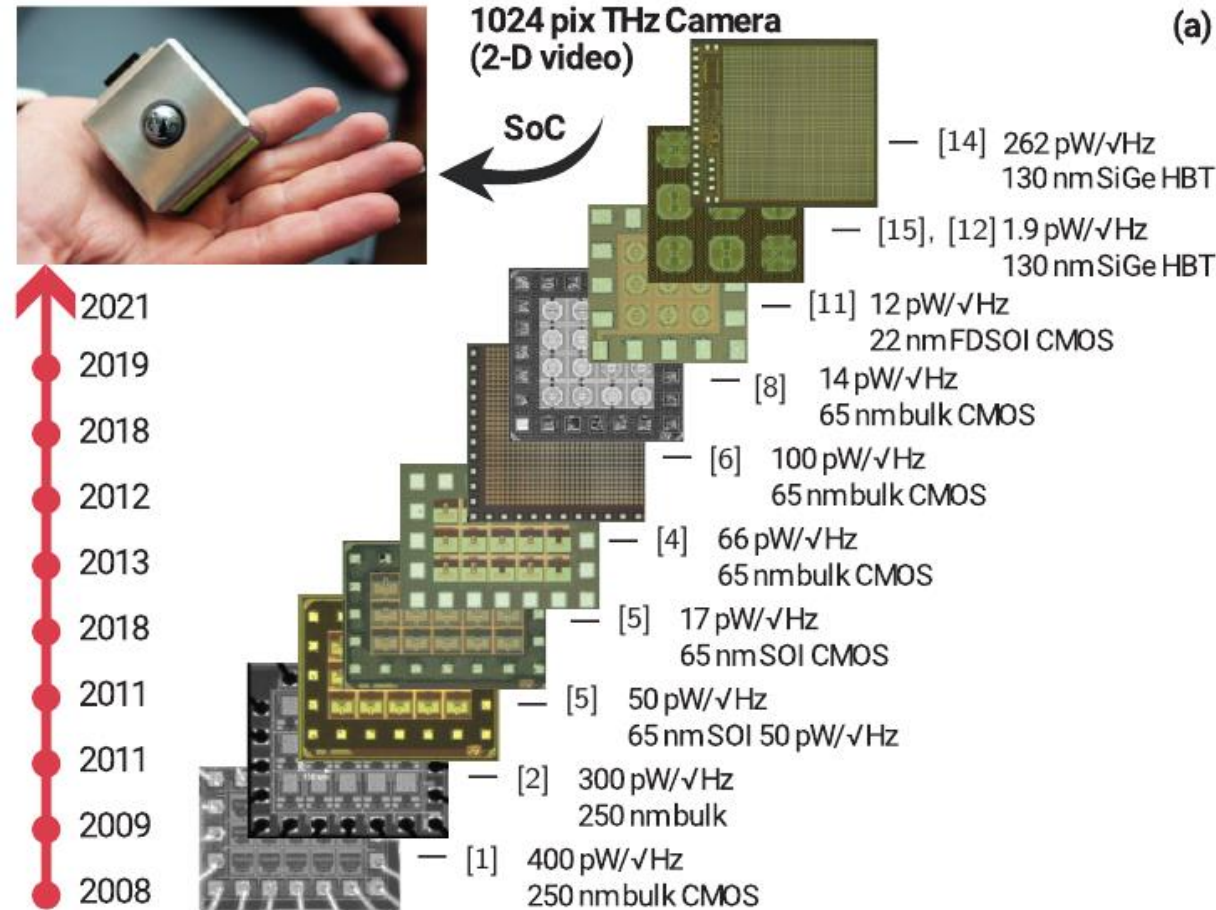
Coherent System: High imaging SNR even at 1THz possible!

How about in-coherent imager?

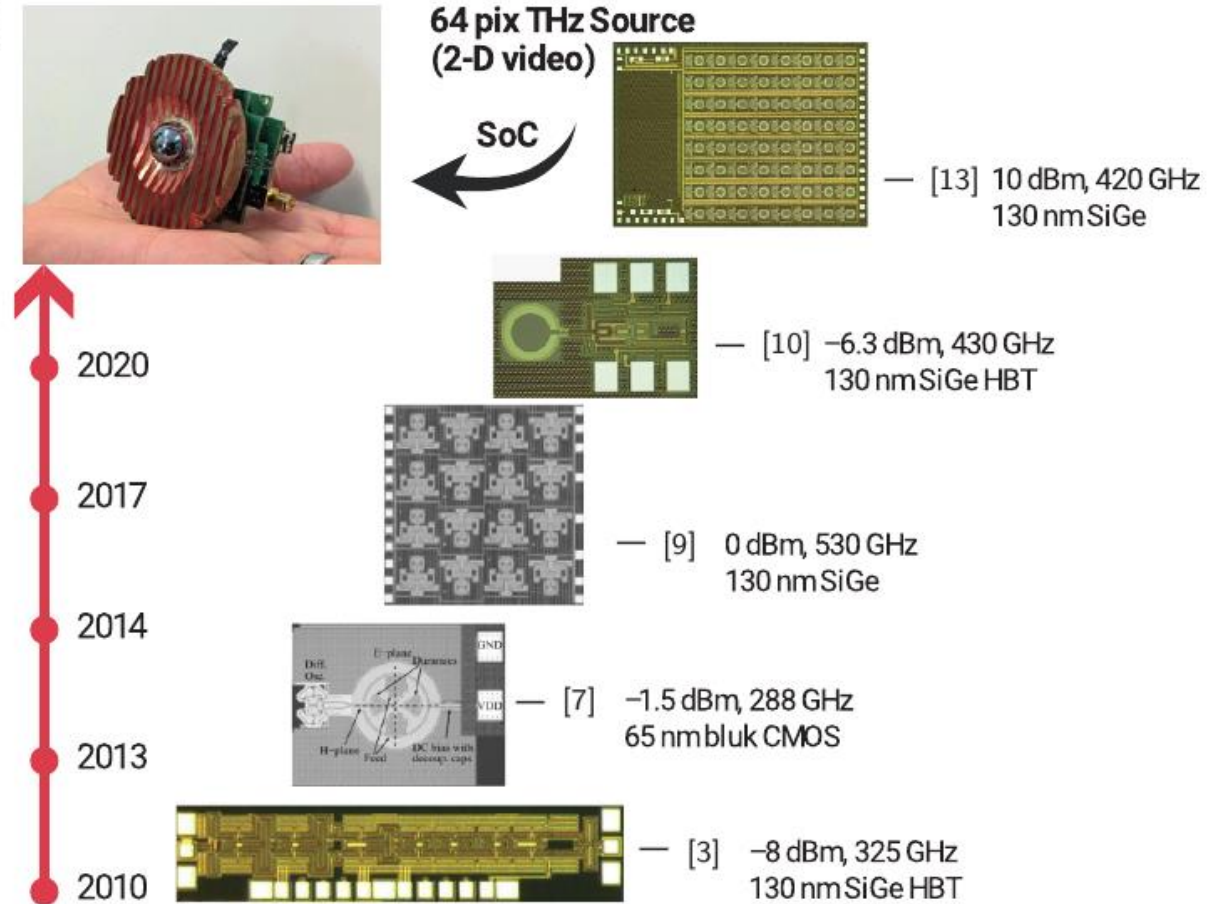
Example 2: THz Imaging

Past work on THz incoherent detectors and THz sources

NEP IMPROVED BY 2 ORDERS OF MAGNITUDE IN 10 YEARS!



RADIATED POWER INCREASED BY 2 ORDERS OF MAGNITUDE IN 10 YEARS!



Commercial THz CMOS USB Camera

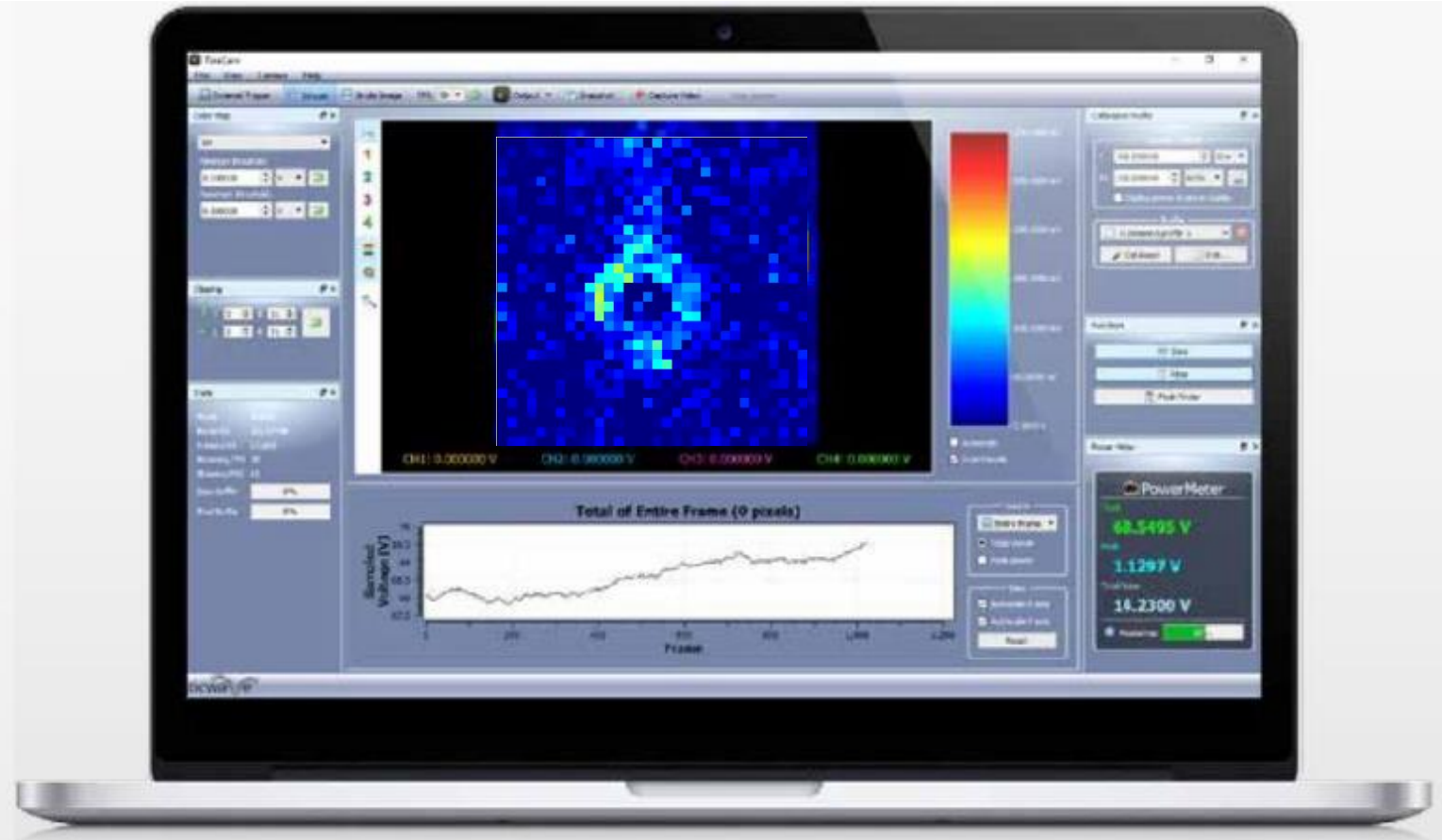
- 1 THz real-time demo at VDI both at IMS 2017



External
trigger input

Mini
USB port

Frame
trigger output



ST 65nm bulk CMOS

Courtesy TicWave (Camera) and VDI (1THz Source)

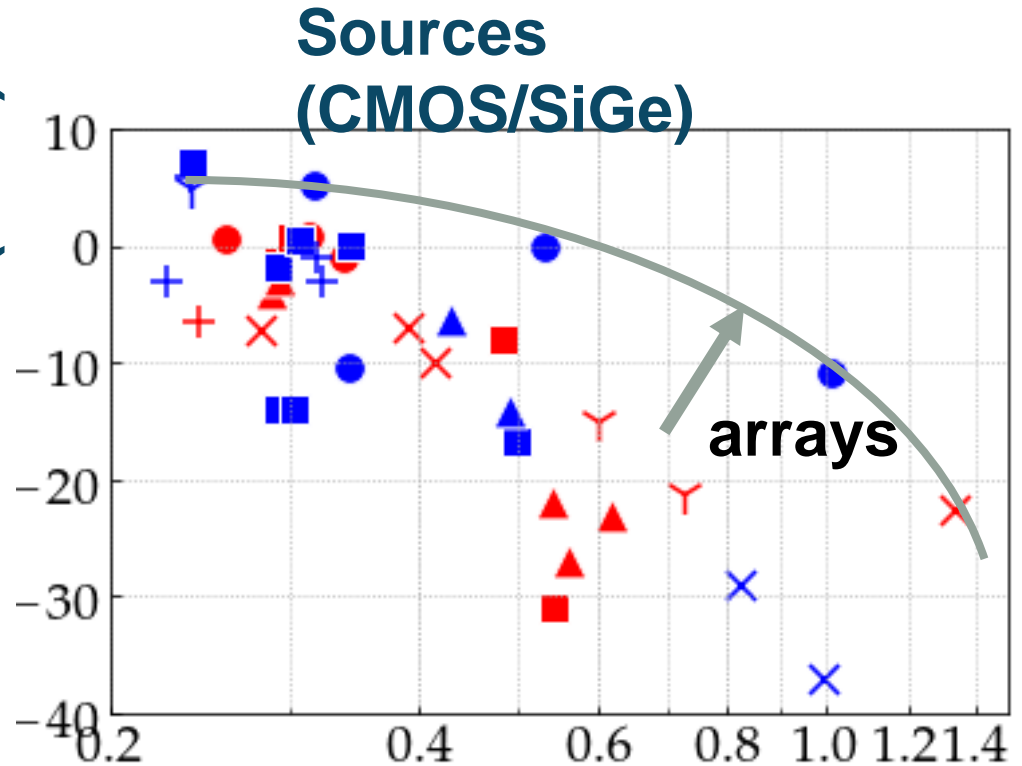
1. Improve performance (Devices to Components)

ST 65nm bulk CMOS

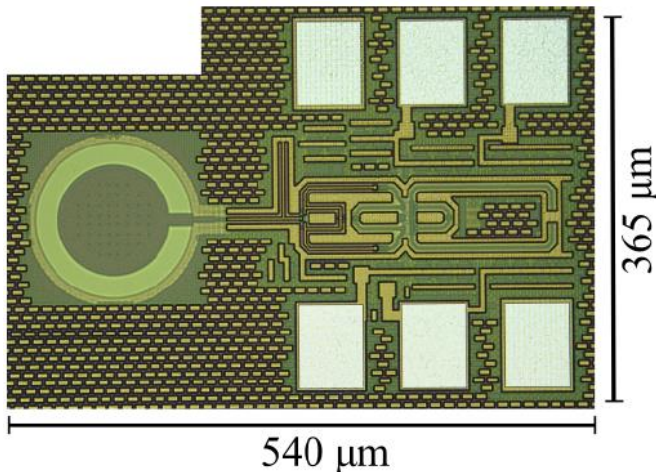


3-push ring OSC
-4dBm@288GHz
PN@10MHz: -93dBc/Hz
DC to RF: 0.15%

Radiated Power (dBm)



IHP 130nm SiGe



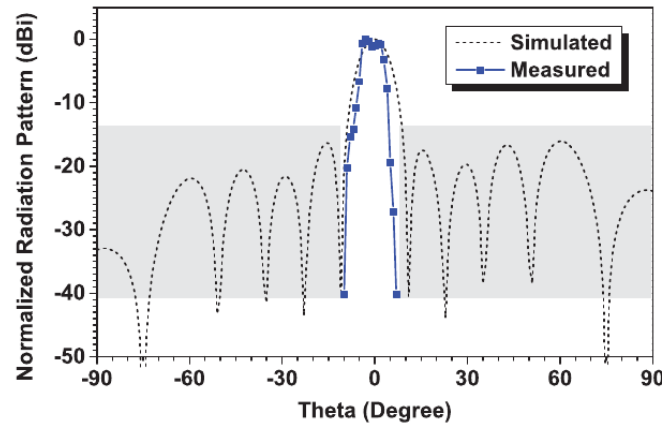
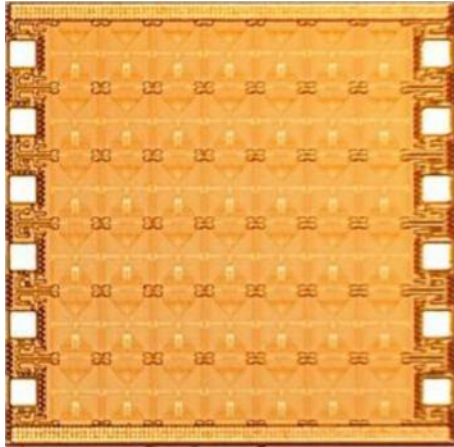
VCO+doubler
-6.3dBm@430GHz
PN@10MHz: -89dBc/Hz
DC to RF: 0.14%

[1] P. Hilger, A Lens-Integrated 430 GHz SiGe HBT Source With Up to -6.3 dBm Radiated Power, RFIC 2017

| | | | |
|---|-----------------------|---|-----------------------|
| ■ | CMOS Osc.(on-chip) | ■ | SiGe Osc.(on-chip) |
| ▲ | CMOS Osc.(radiating) | ▲ | SiGe Osc.(radiating) |
| ● | CMOS Osc.(rad. array) | ● | SiGe Osc.(rad. array) |
| + | CMOS Mul.(on-chip) | + | SiGe Mul.(on-chip) |
| Y | CMOS Mul.(radiating) | Y | SiGe Mul.(radiating) |
| X | CMOS Mul.(rad. array) | X | SiGe Mul.(rad. array) |

Silicon Source Arrays (Coherent vs. Incoherent)

Coherent Radiators



91 elements

OSC 4-push

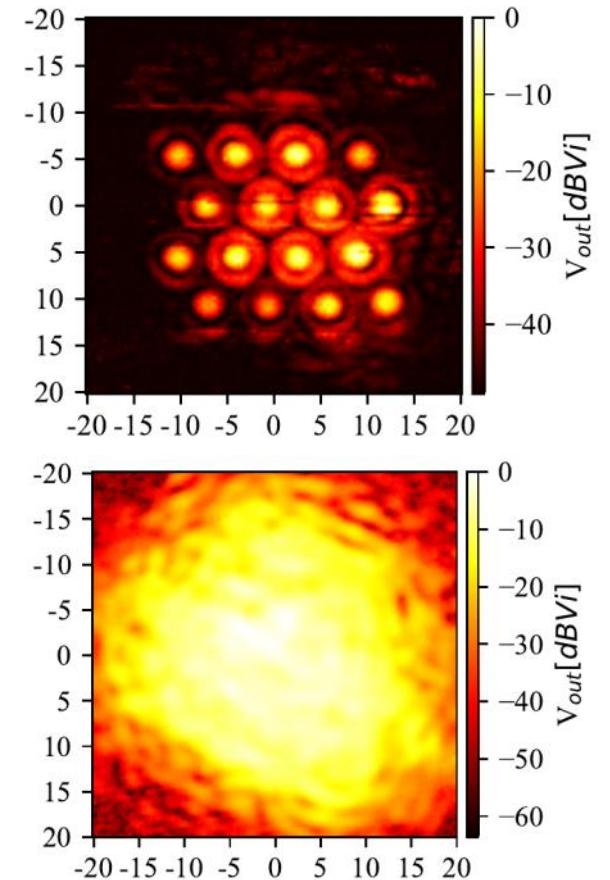
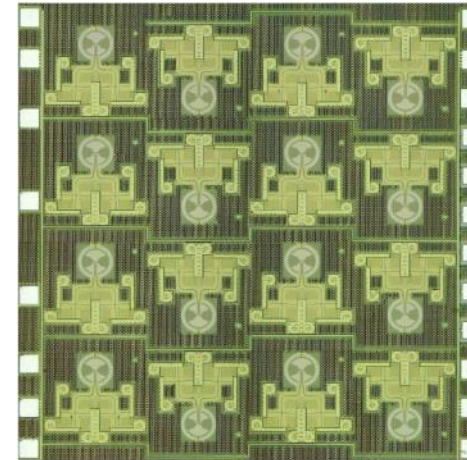
-10.9dBm @ 1.01 THz

DC to RF: 0.0073%

IHP 130nm SiGe

[1] Zhi Hu et.al., High-Power Radiation at 1 THz in Silicon: A Fully Scalable Array Using a Multi-Functional Radiating Mesh Structure, JSSC 2018

Incoherent Radiators



16 elements

OSC 3-push

0dBm @530GHz

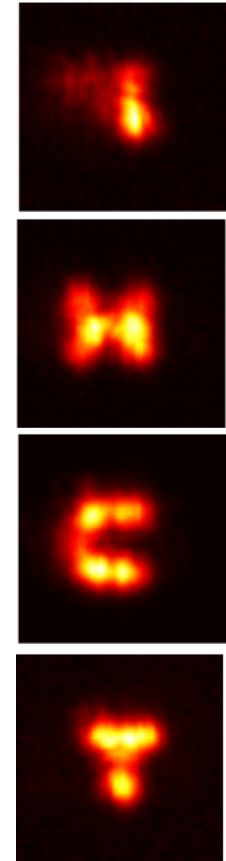
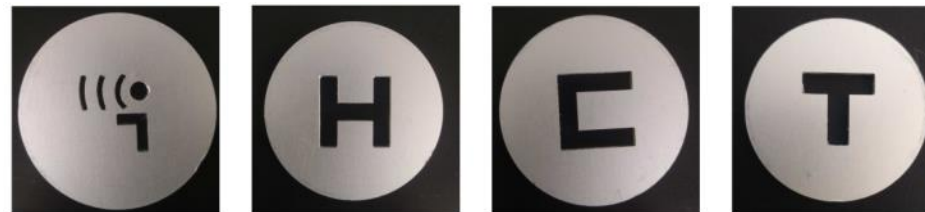
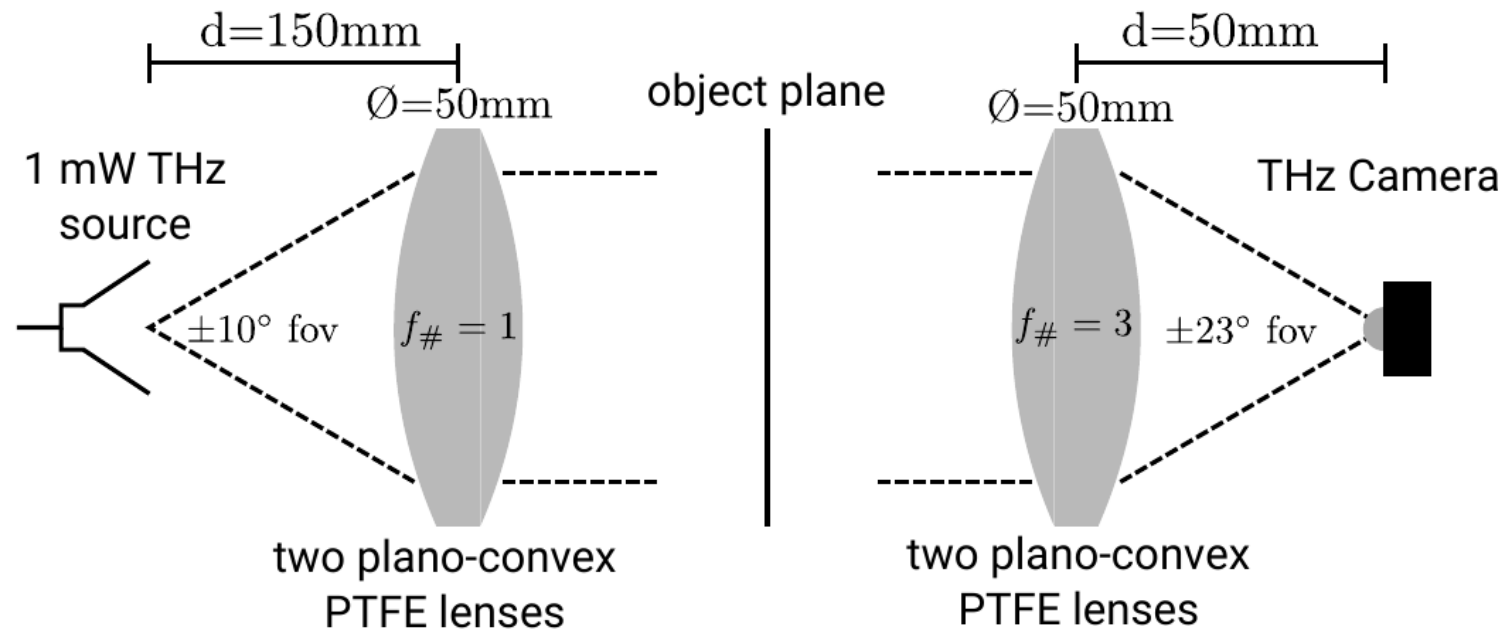
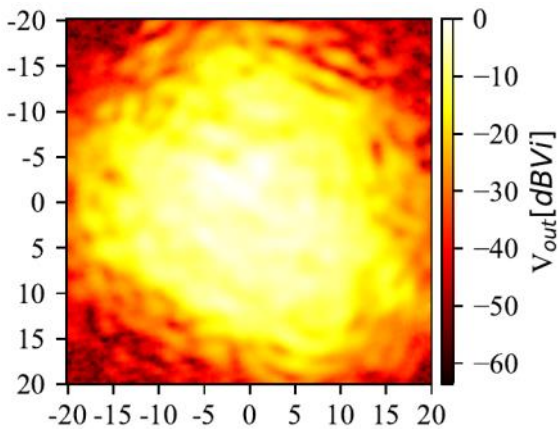
DC to RF: 0.04%

IHP 130 nm SiGe

[1] U. Pfeiffer, et al., A 0.53 THz reconfigurable source module with up to 1 mW radiated power for diffuse illumination in terahertz imaging applications, JSSC 2014

Diffused Illumination

1mW $\frac{1}{2}$ THz diffuse illumination

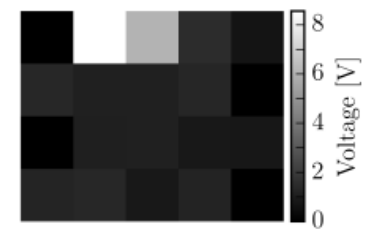
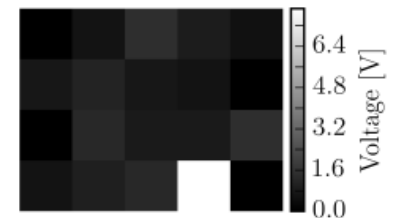
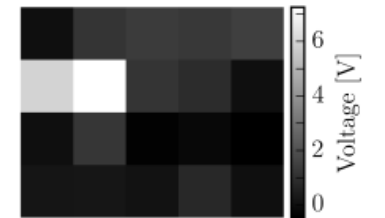
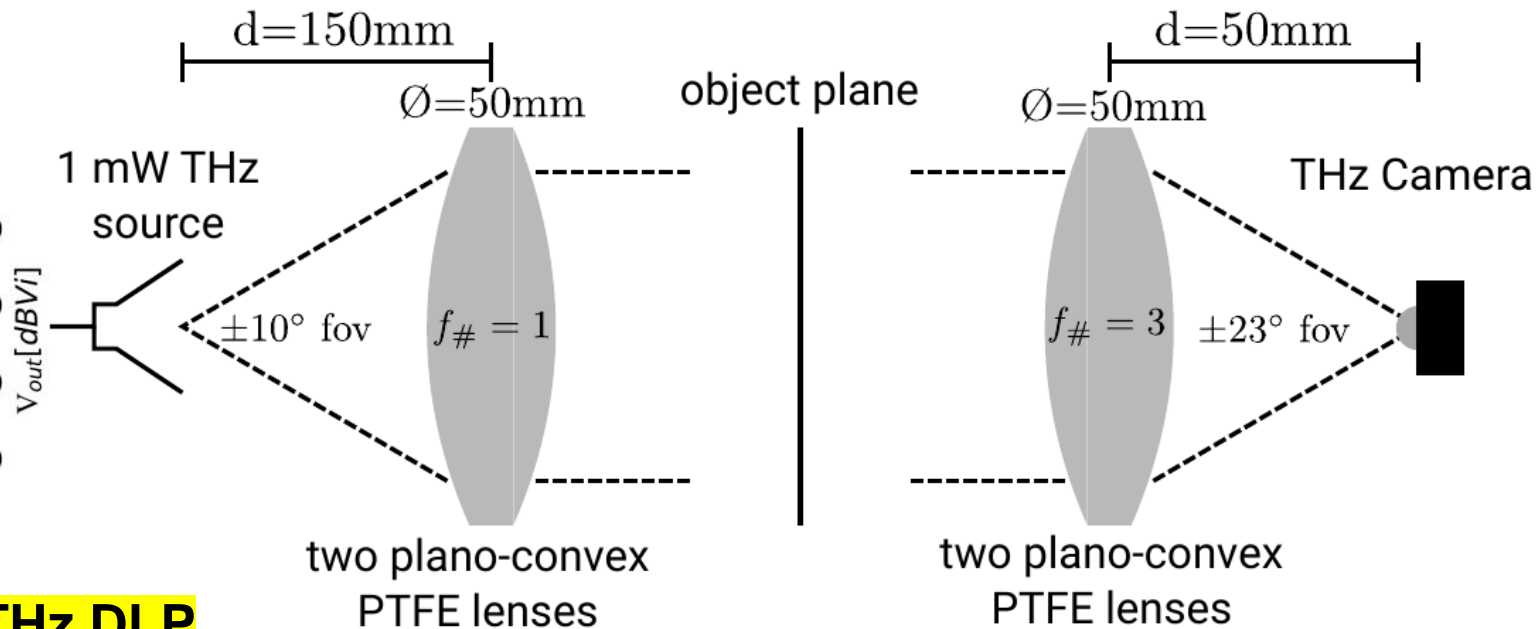
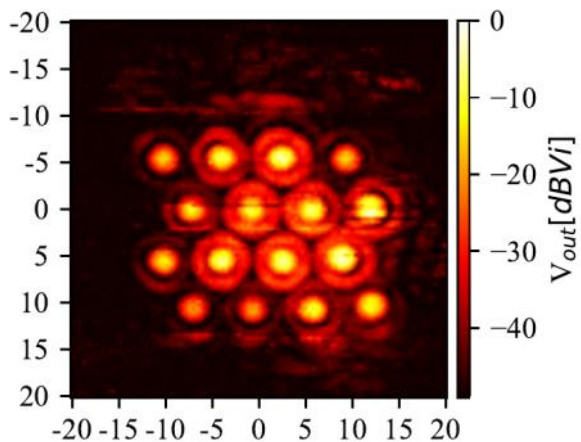


[1] D. Headland et.al., Diffuse beam with electronic terahertz source array, IRmmW-THz 2018

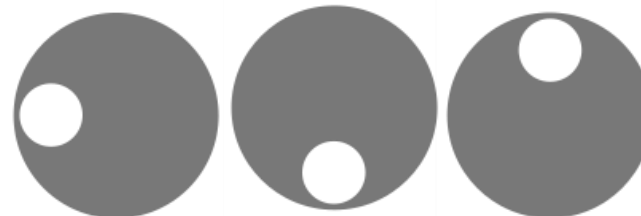
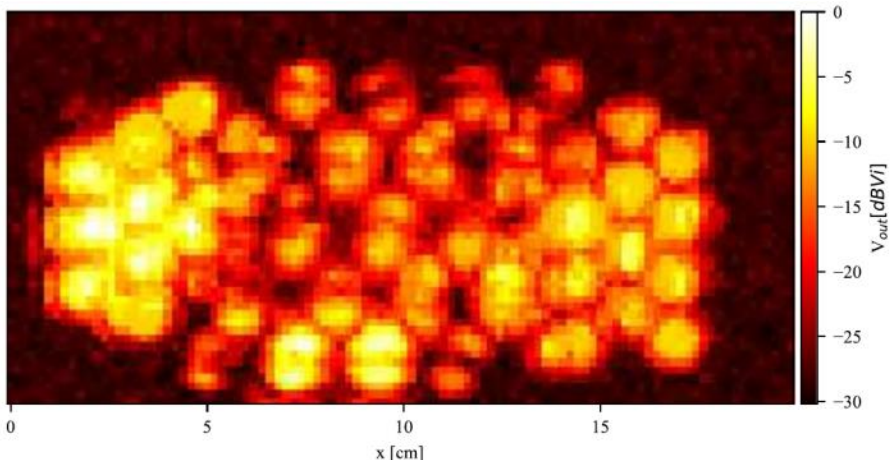
Computational Imaging and Diffused Illumination

Computational imaging

1mW 1/2 THz digital light processor



4mW 62 pixel THz DLP



Applications With Silicon-Based

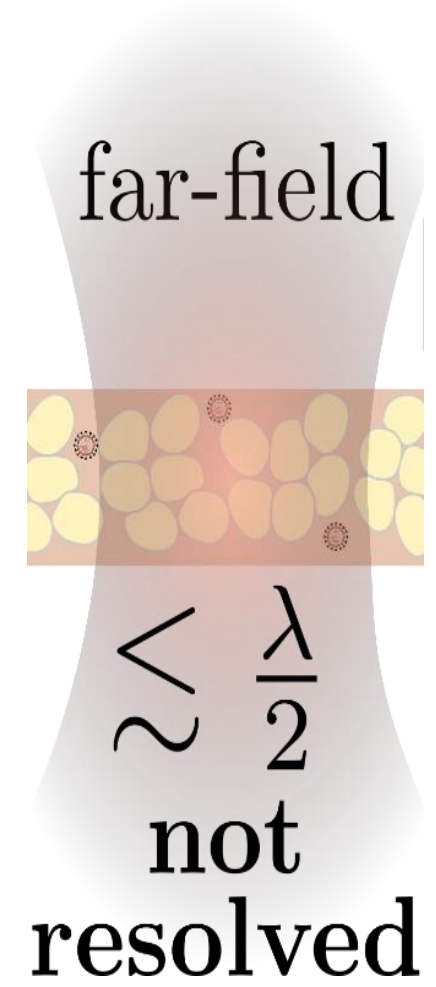
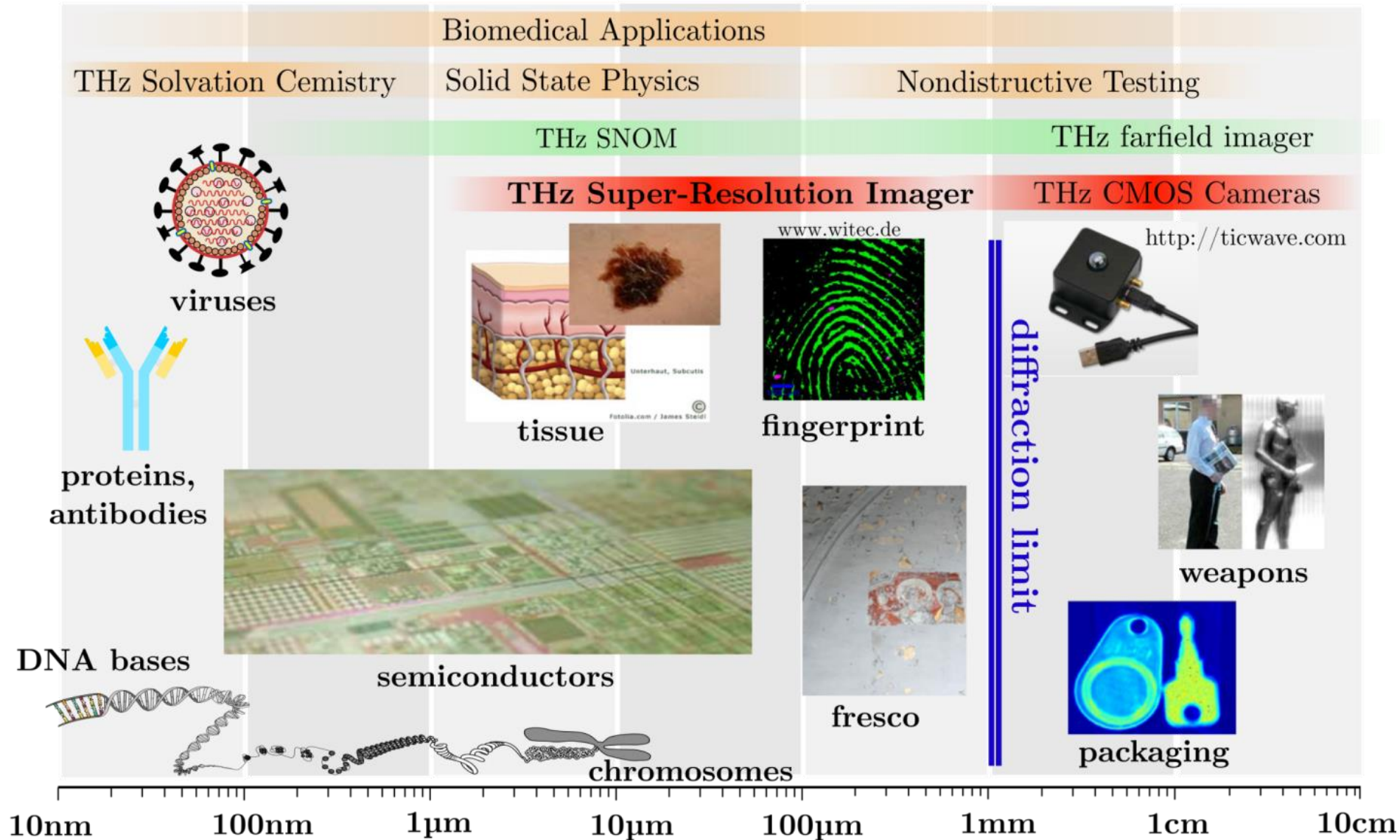
ge-growth construction of LDPC codes
onal Workshop on Compressed

- On-the-fly APEG-LDPC sensing matrix generation
- OMP reconstruction
 - Compression ratio $\leq 50\%$

Example 3: THz Near-Field Imaging

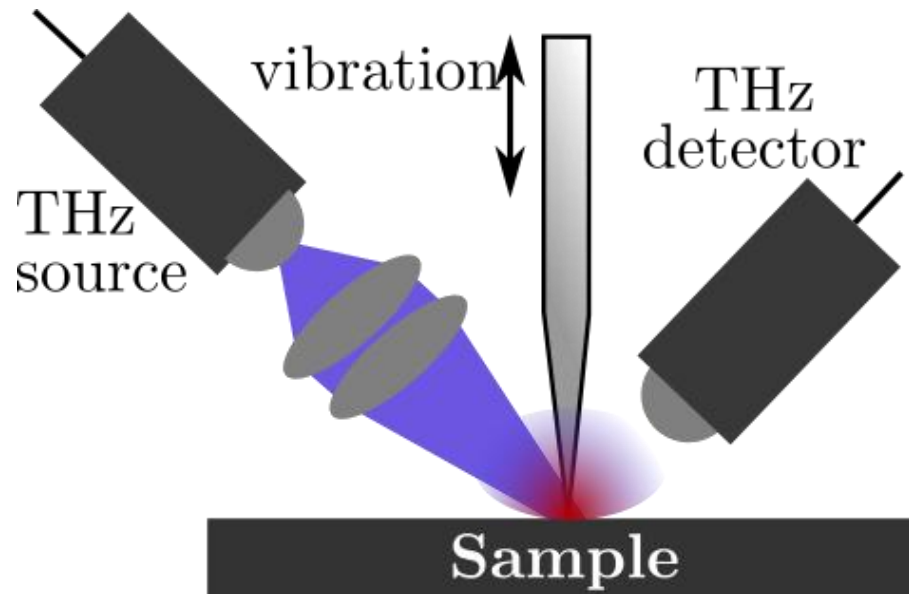
However, resolution is diffraction limited...

Feature sizes of THz imaging/sensing objects



SoA Near-Field Imaging

Near-Field Scanning Optical Microscopy (NSOM)



$\mu\text{m}/\text{nm}$ -range resolution

Source or detector placed remotely

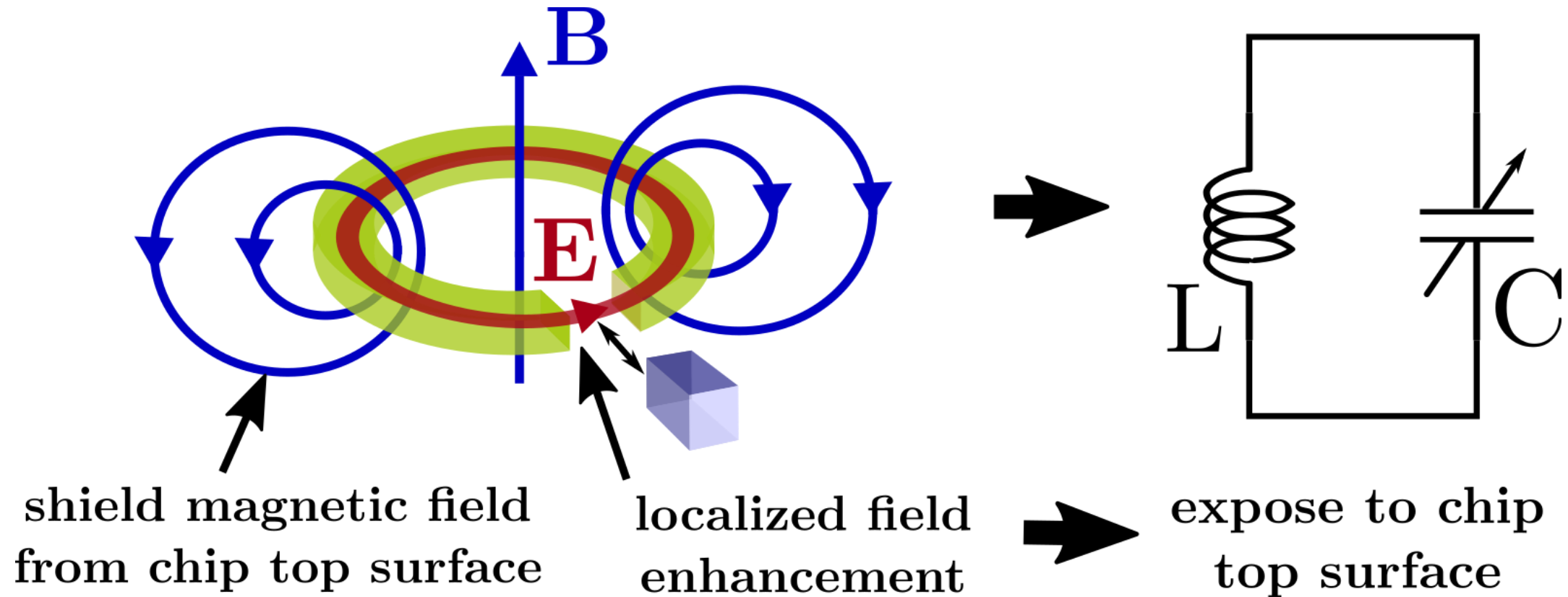
- Poor power coupling efficiency
- High-power sources & cooled detectors
- Low dynamic range & contrast in far-field clutter



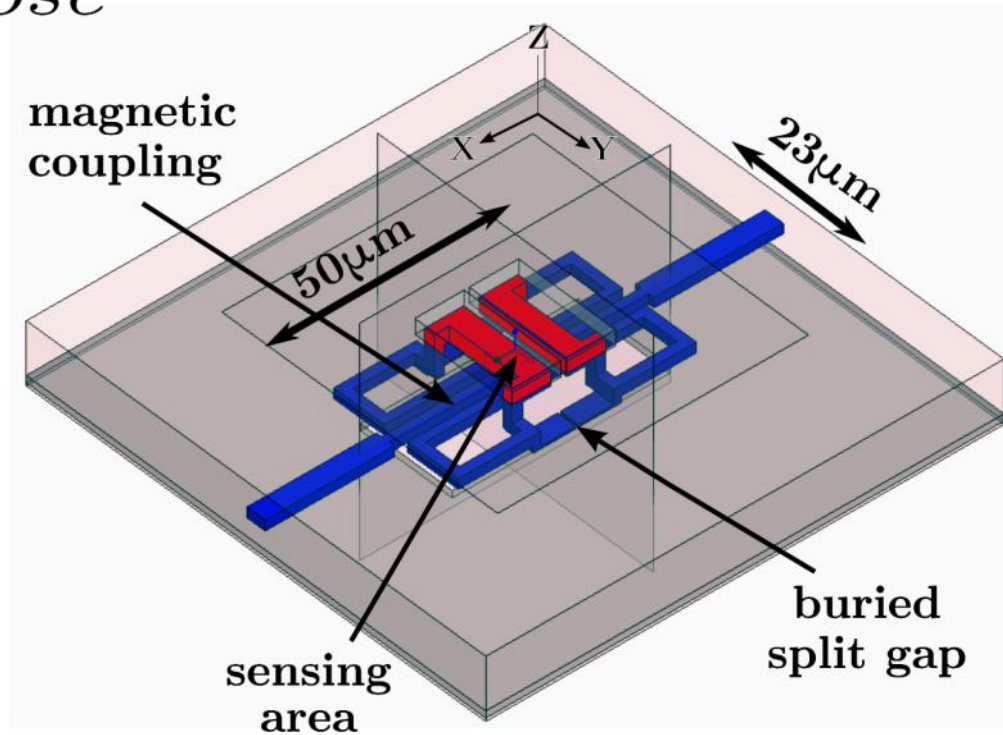
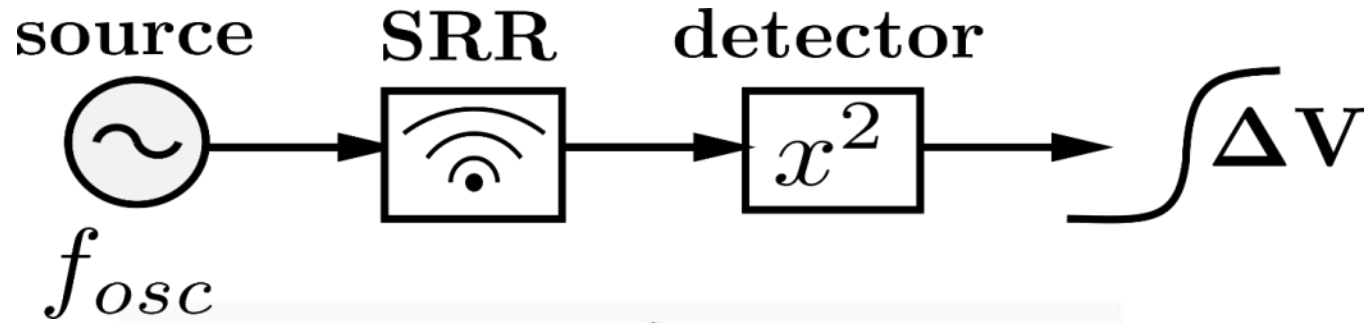
Laboratory technique

Sensing Mechanism

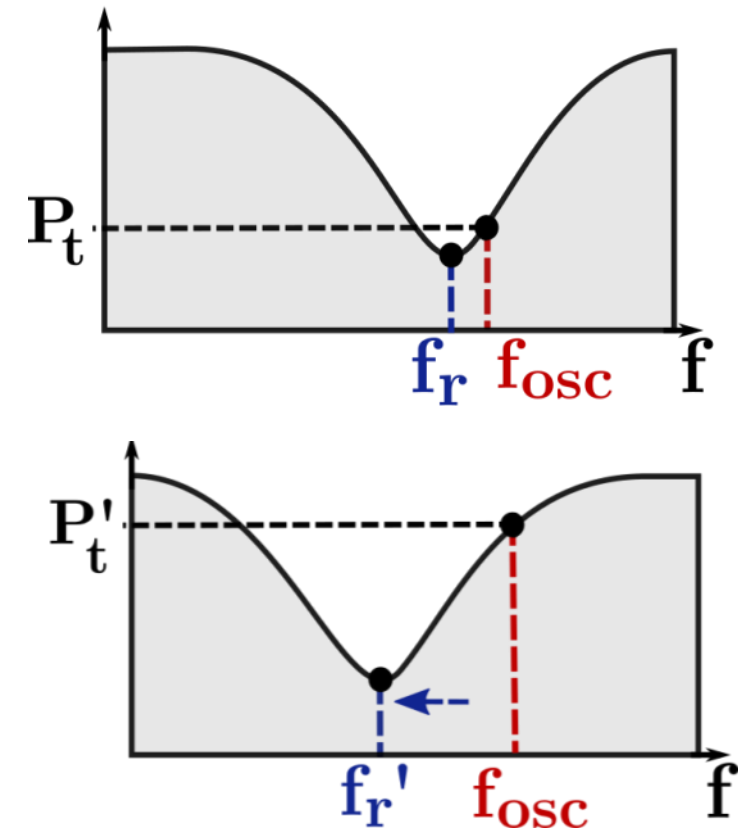
Split-ring resonator (SRR)



Resonator Design

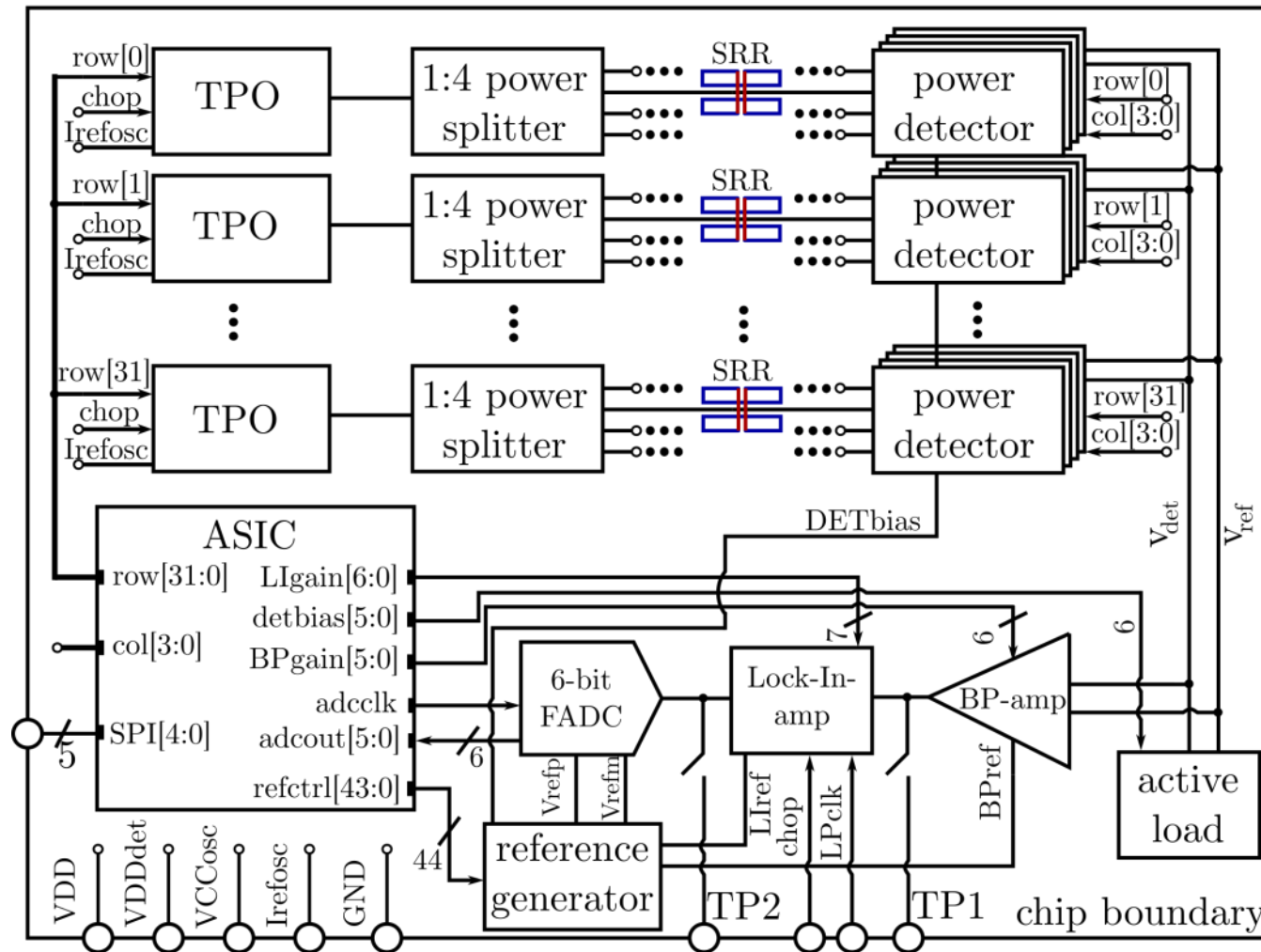


Free-running oscillator and power detector



[1] Janusz Grzyb et.al. A 0.55 THz Near-Field Sensor With a μm -Range Lateral Resolution Fully Integrated in 130 nm SiGe BiCMOS, JSSC 2016

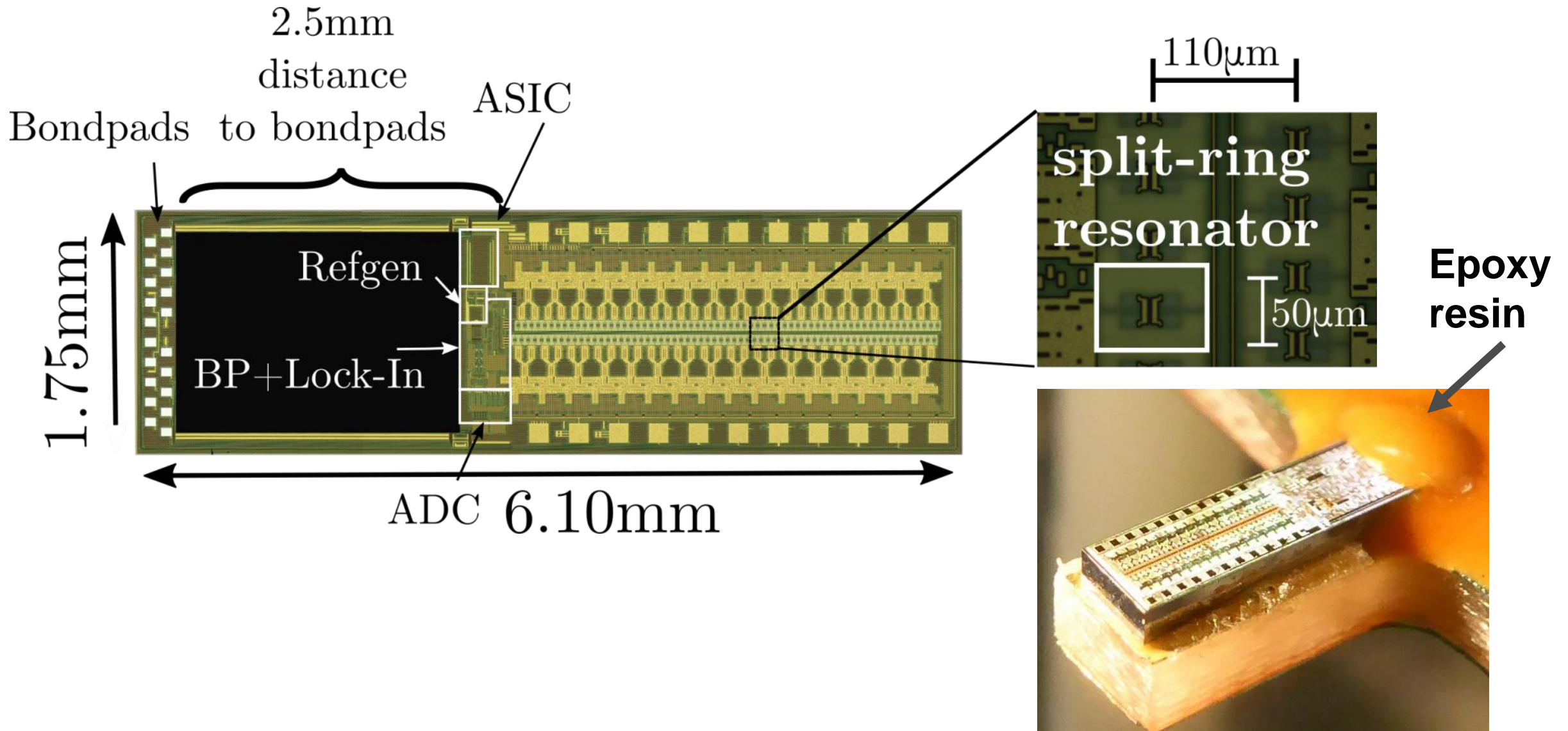
128-pixel Near-field Imager (THz SoC)



- IHP 0.13 μm SiGe-BiCMOS (fT/fmax=300/450GHz)
- Each row divided into 16 sub-arrays of 4 pixels
- Driven from single triple-push oscillator
- Connected by 4-way power splitter
- Sequential operation

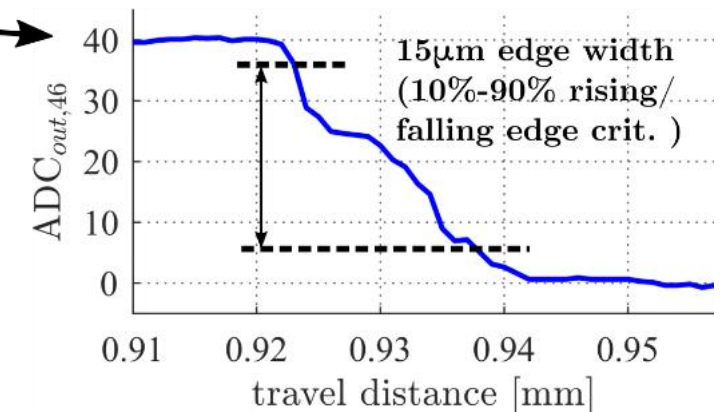
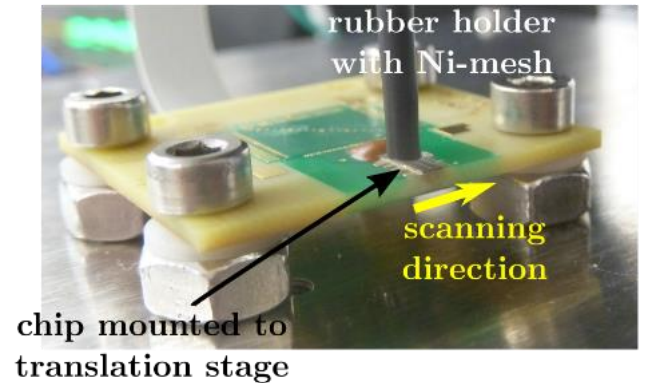
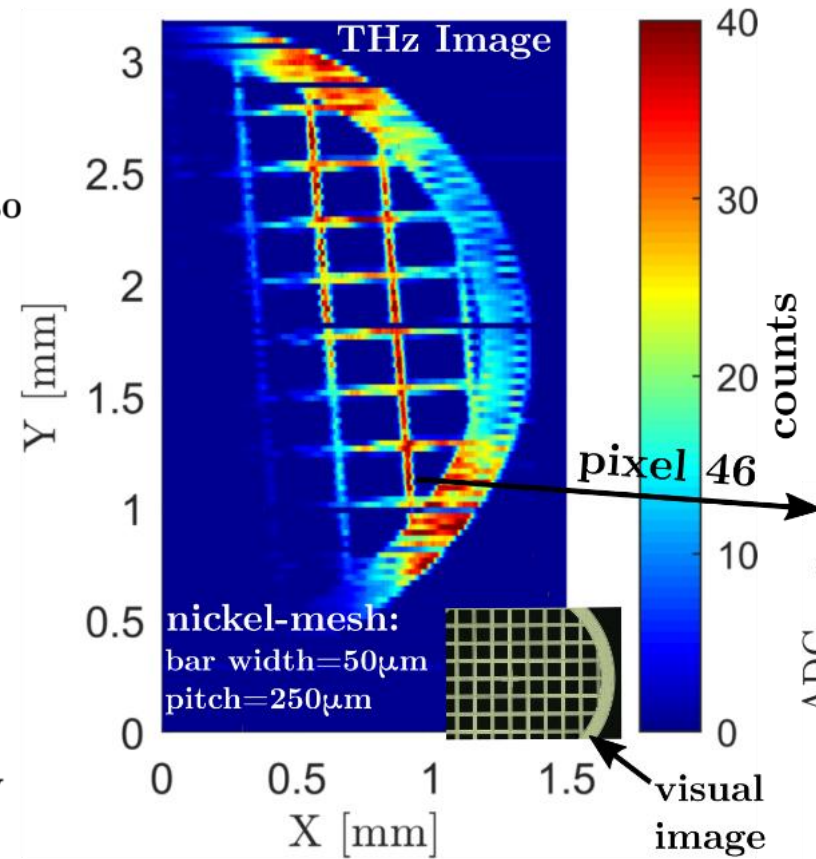
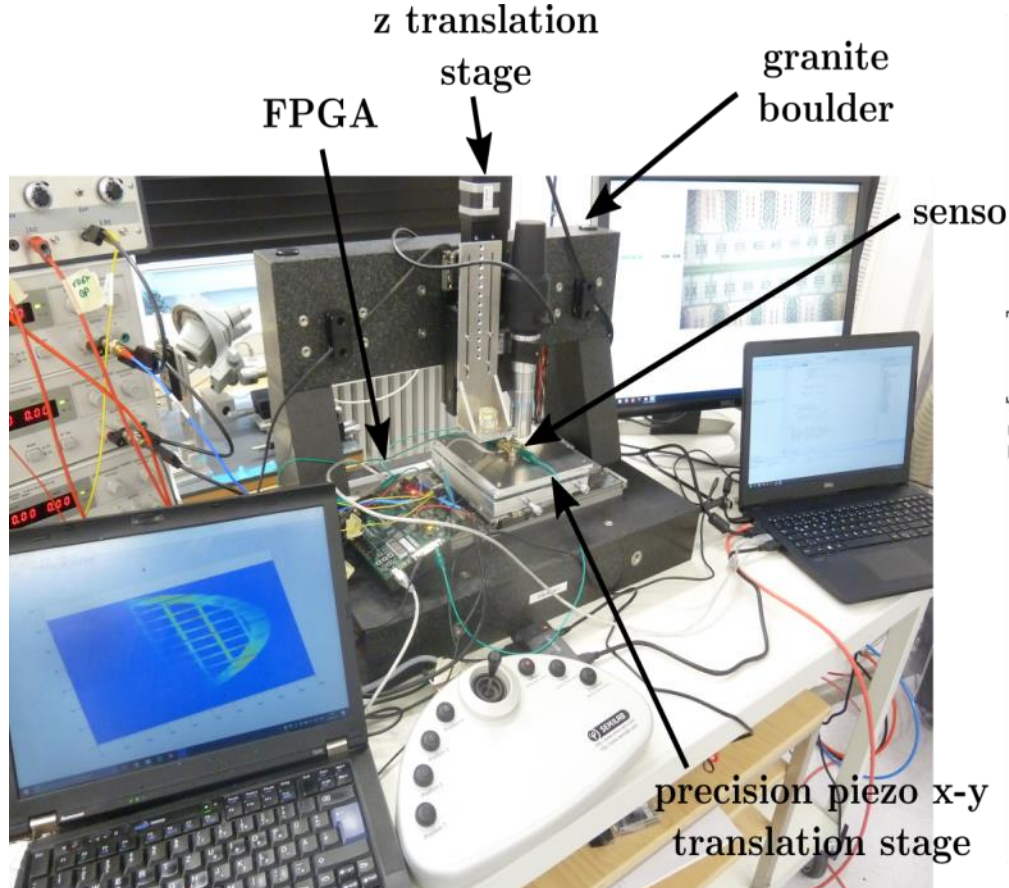
[1] P. Hillger et al. , A 128-pixel 0.56THz sensing array for real-time near-field imaging in 0.13 μm SiGe BiCMOS, ISSCC 2018

Chip Micrograph and Packaging



Imaging Results

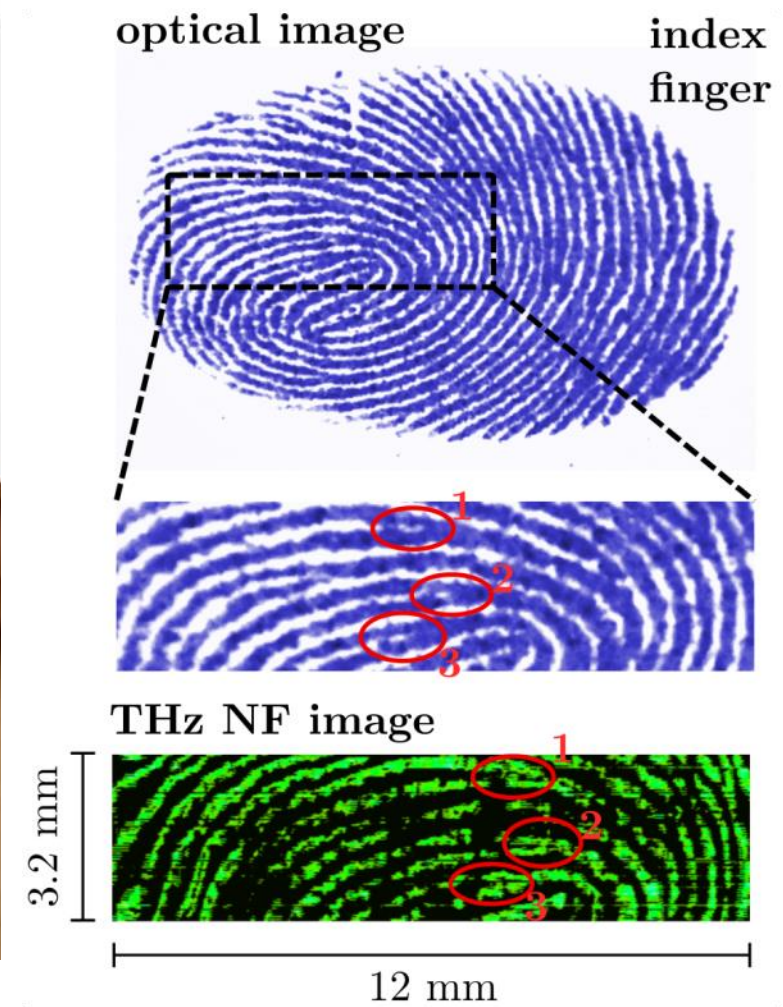
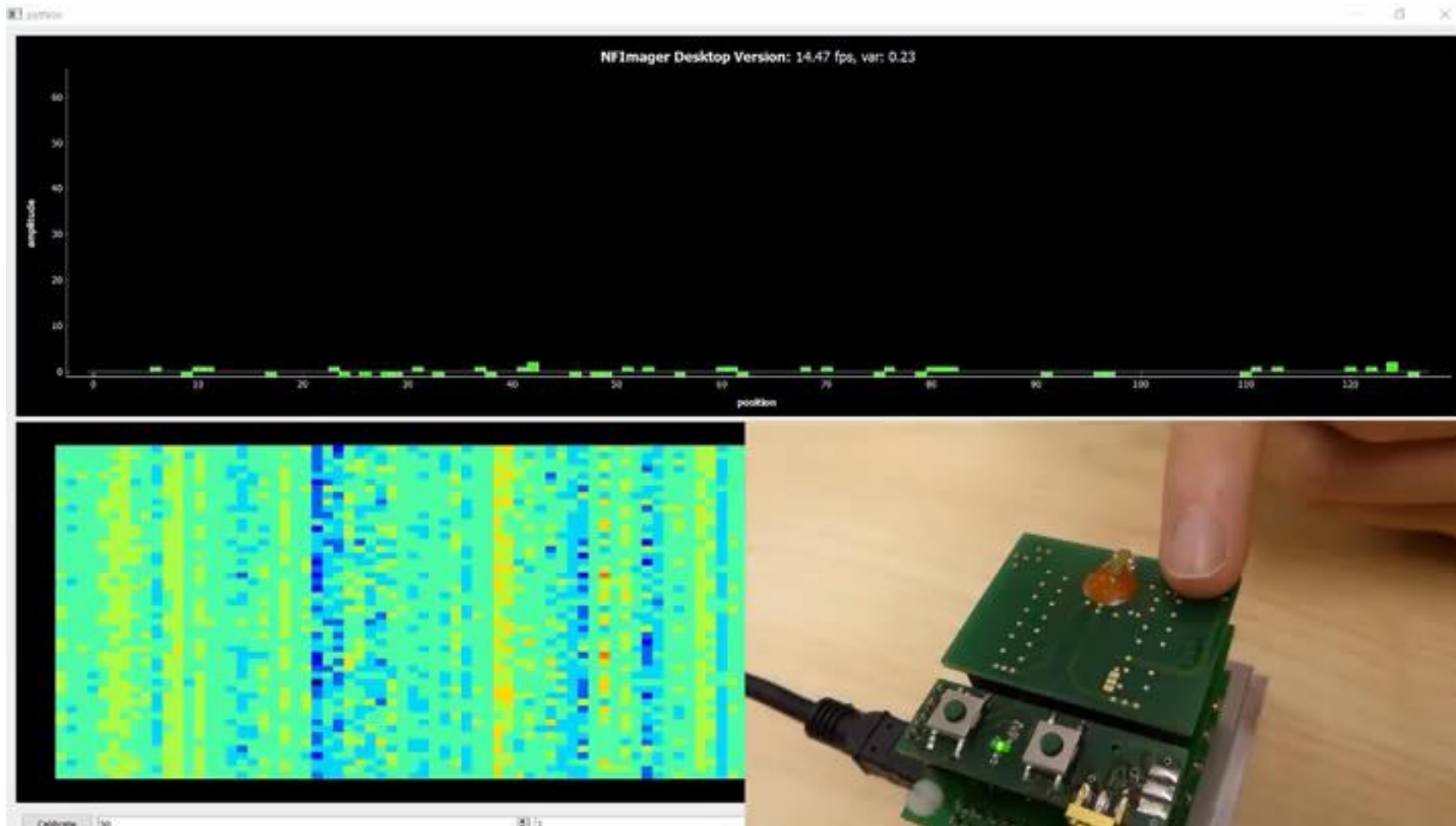
Main Challenge: Mechanical stability / accuracy



128x1500 pixel (1-D scan, 1 μ m step)

T_{scan}=6min 45 sec !

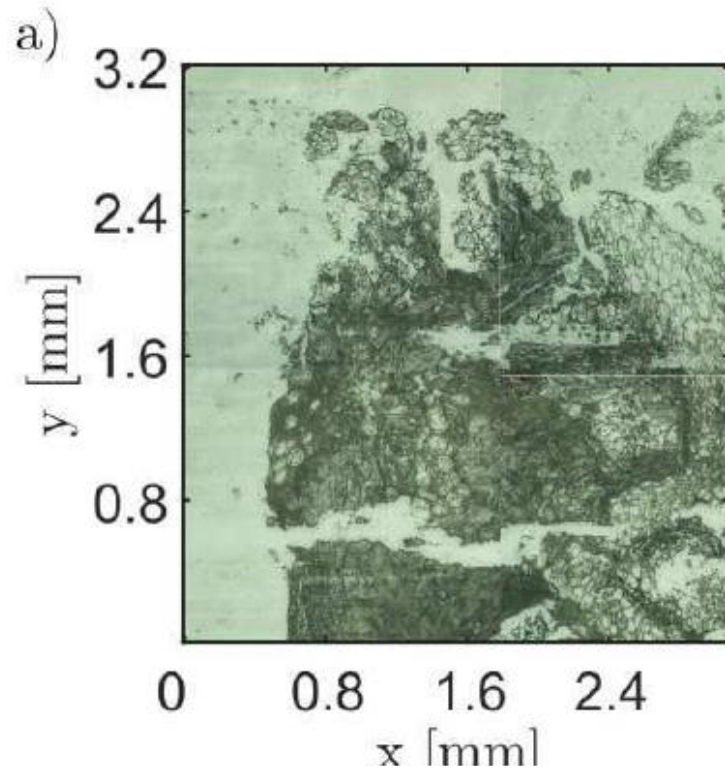
Real-time Near-field Imaging



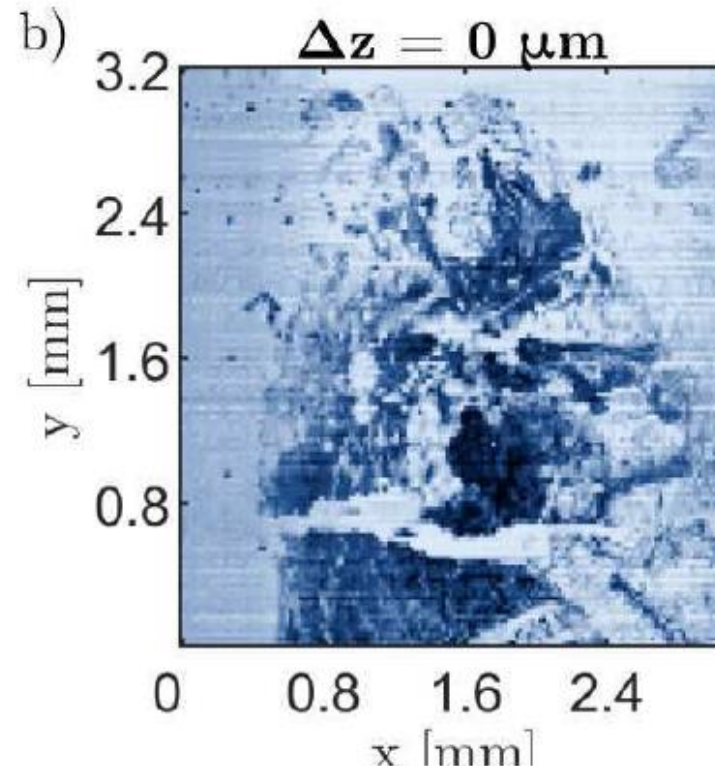
842x128 pixel Tscan=30 sec !

Outlook – Biomedical Applications

Microscopic Image



THz NF Image



- Direct contact
- Image size
142 × 128 pixels
- Pixel pitch
22 μm × 25 μm
- Tstep/Tdwell
2 s/2.5 s

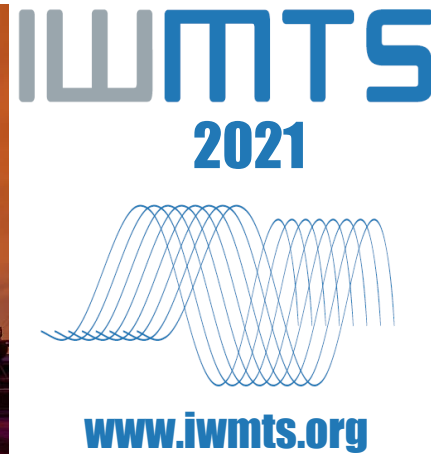
More results to come...

Summary

- THz imaging and sensing applications addressed by large-scale collaborative research projects, 26M€ funded just by the DFG!
- Sensitivity and output power of compact THz cameras and sources have improved by 2 orders of magnitude over the last 10 years!
- Fully integrated THz systems on a chip are feasible today!

Outlook and discussion:

- Imaging and sensing as add on to mobile communications?
- Spectrum sharing with communications?



**2021 Fourth International Workshop on Mobile Terahertz Systems (IWMTS), 5-6 July 2021
Hybrid Workshop taking place in Duisburg, Germany and online**

Deadline Paper submission: February 15th

- Confirmed Key Note Speakers
 - Ian F. Akyildiz, Georgia Institute of Technology, USA
 - Joseph R. Demers, Bakman Technologies, USA
 - Theodore Rappaport, NYU Tandon School of Engineering, USA
 - Mats Pettersson, Blekinge Institute of Technology, Sweden
 - Title: THz SAR - a New Way to Monitor the World
- Panel Session: Will Mobily push THz to Mass Markets?
- TalentTravel Program: Travel Grants available

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